

FIG. 1

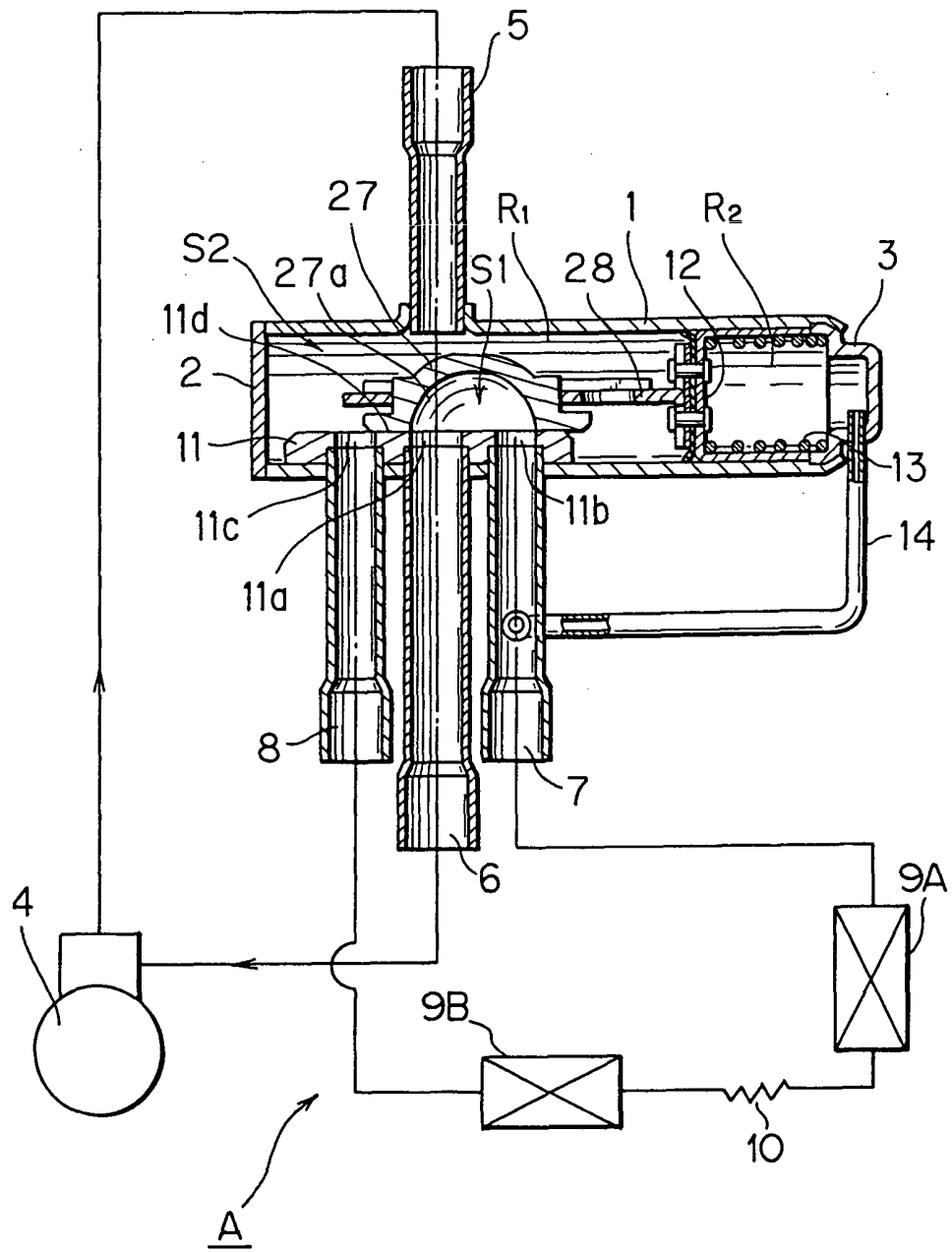
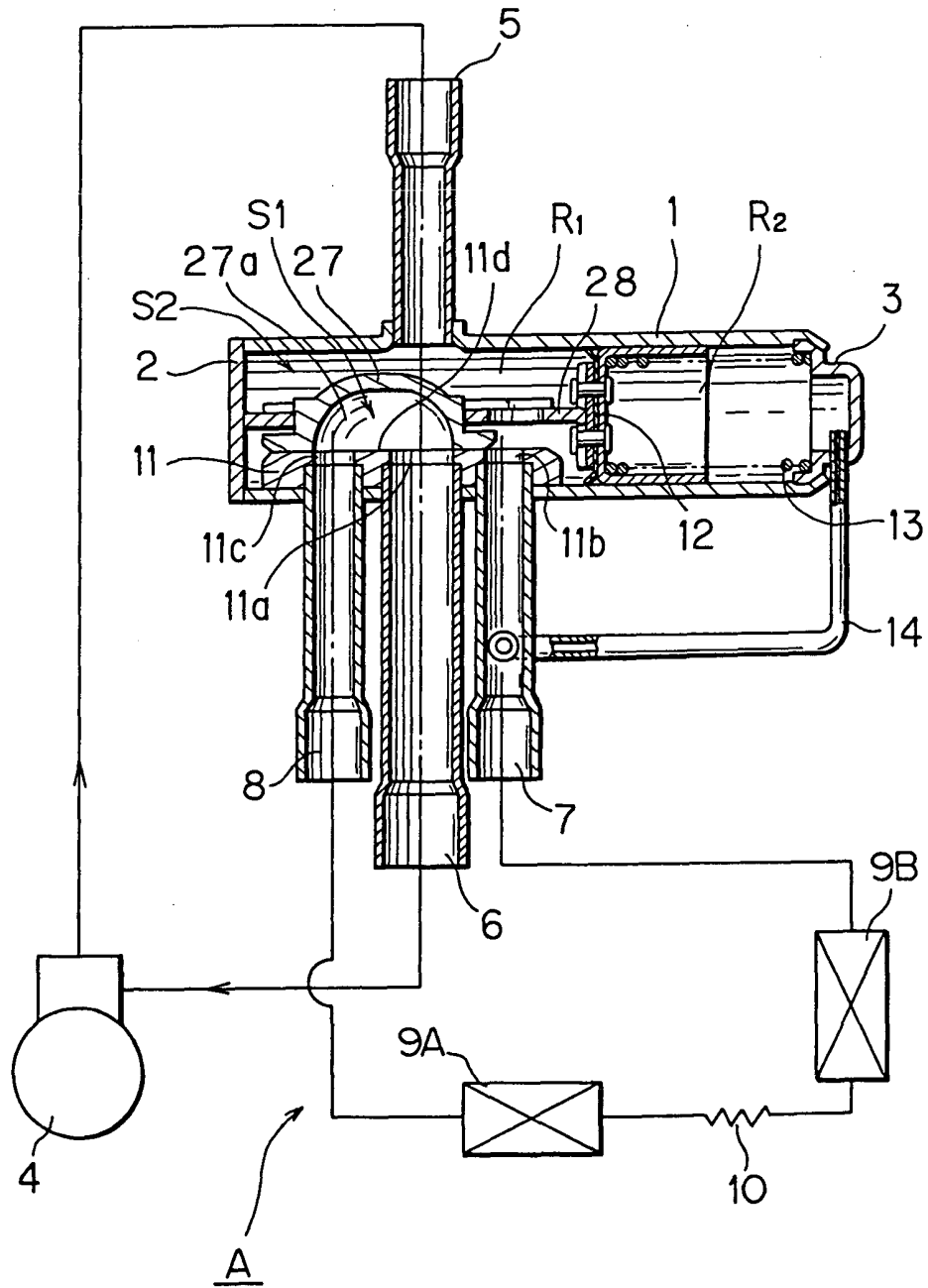


FIG. 2



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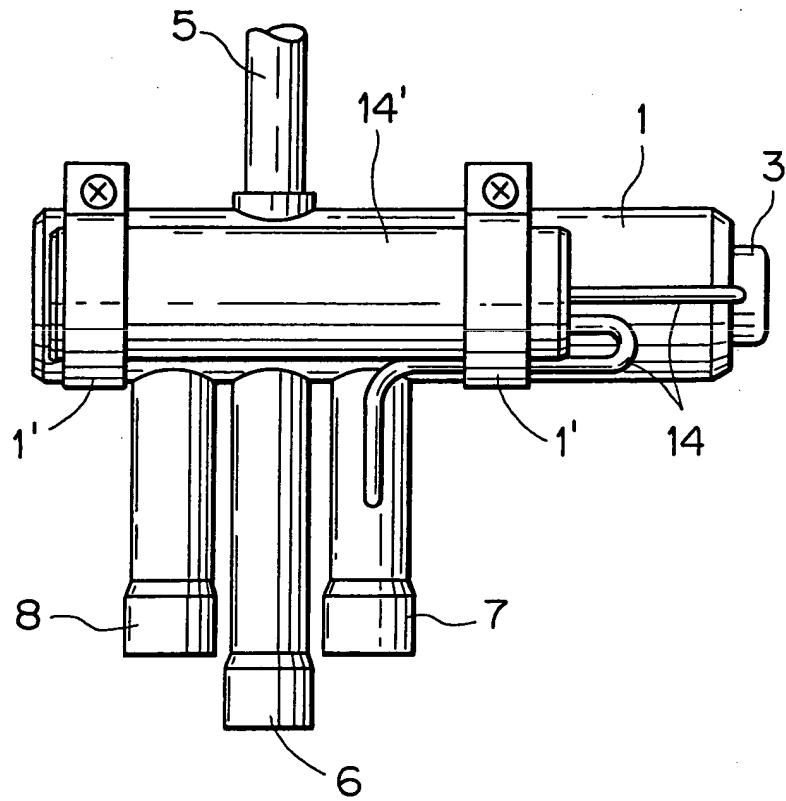


FIG. 4

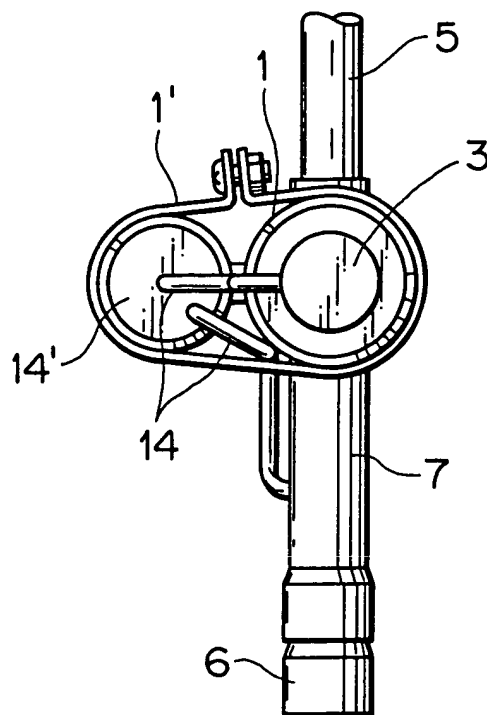
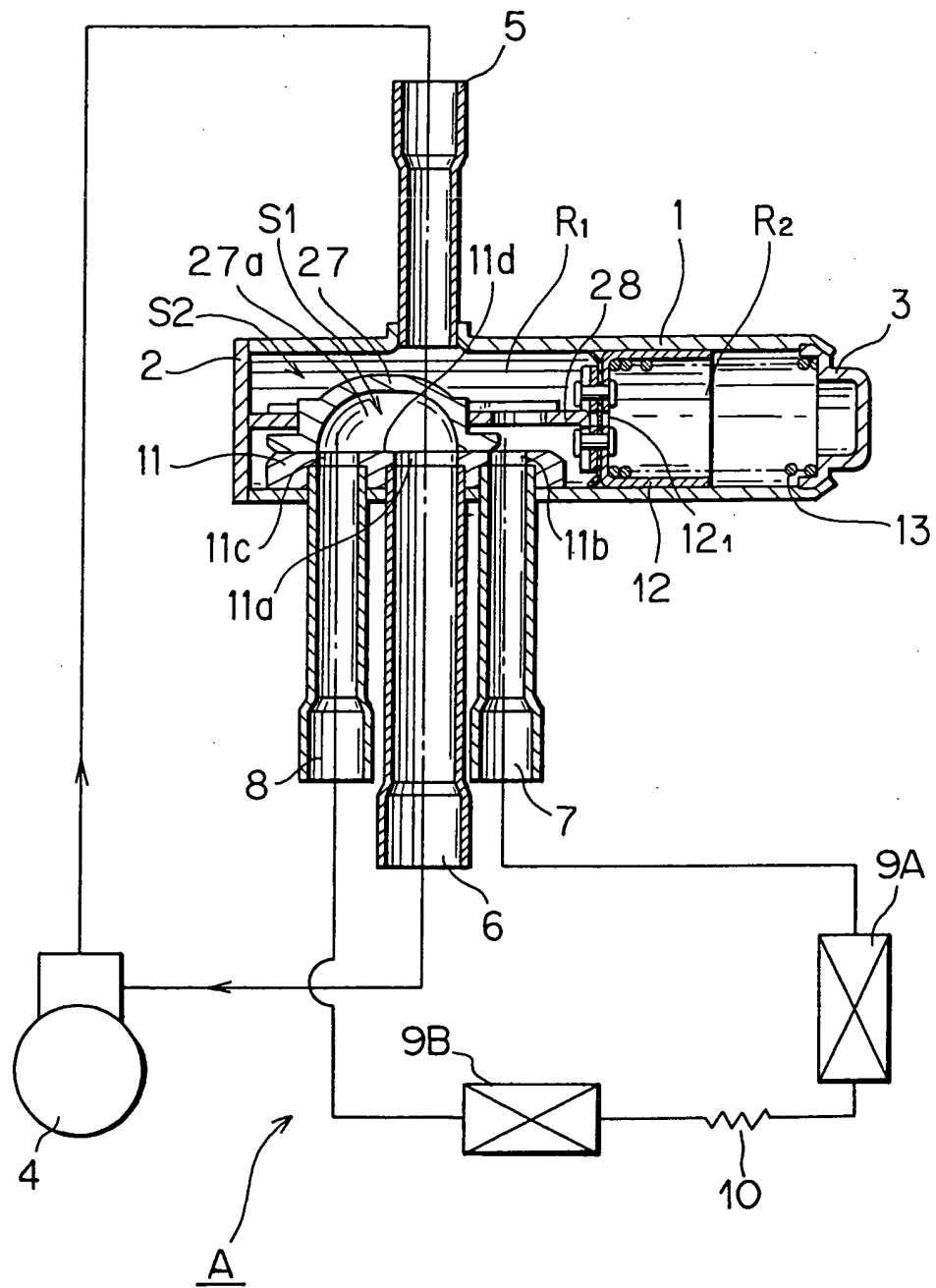


FIG. 5



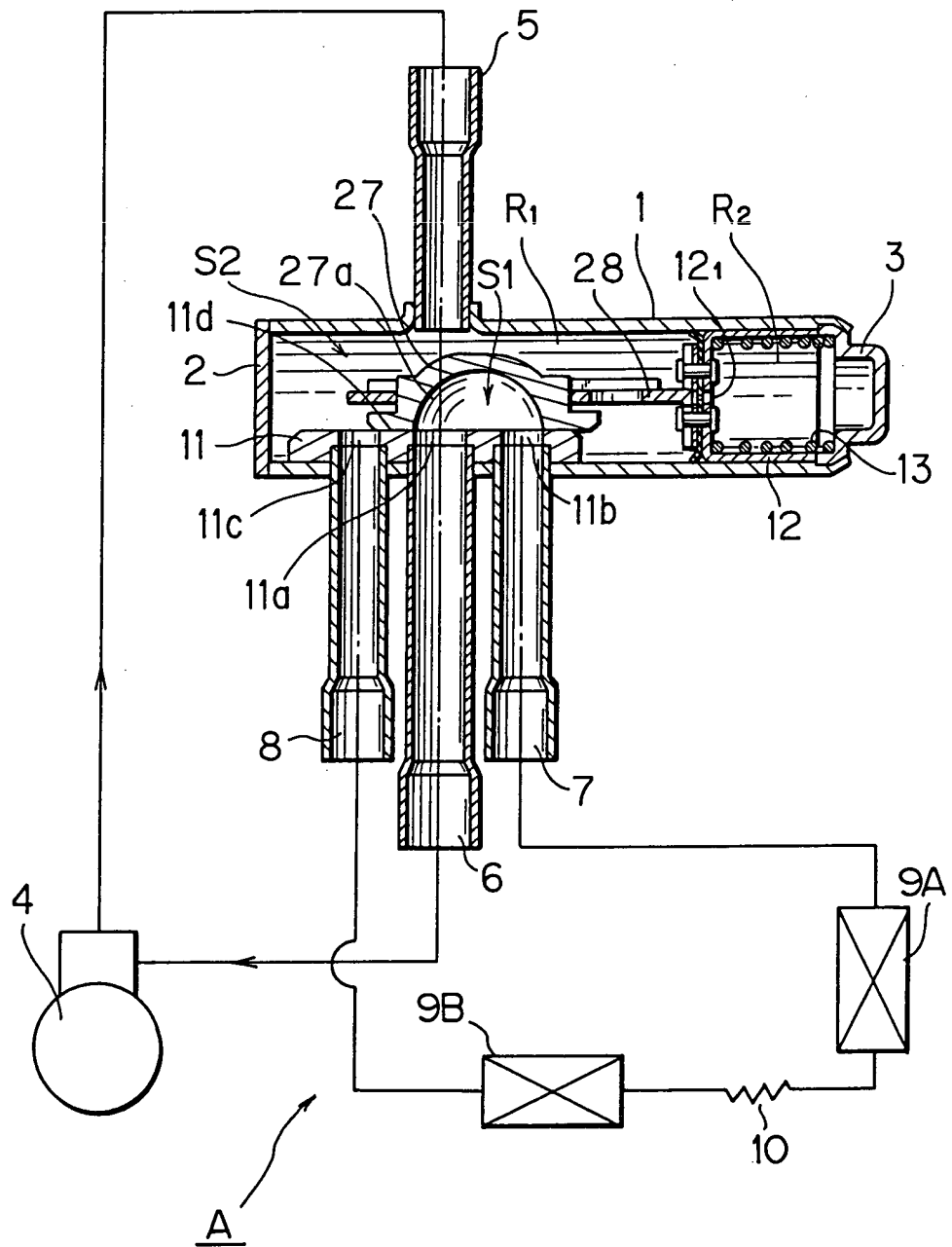


FIG. 7

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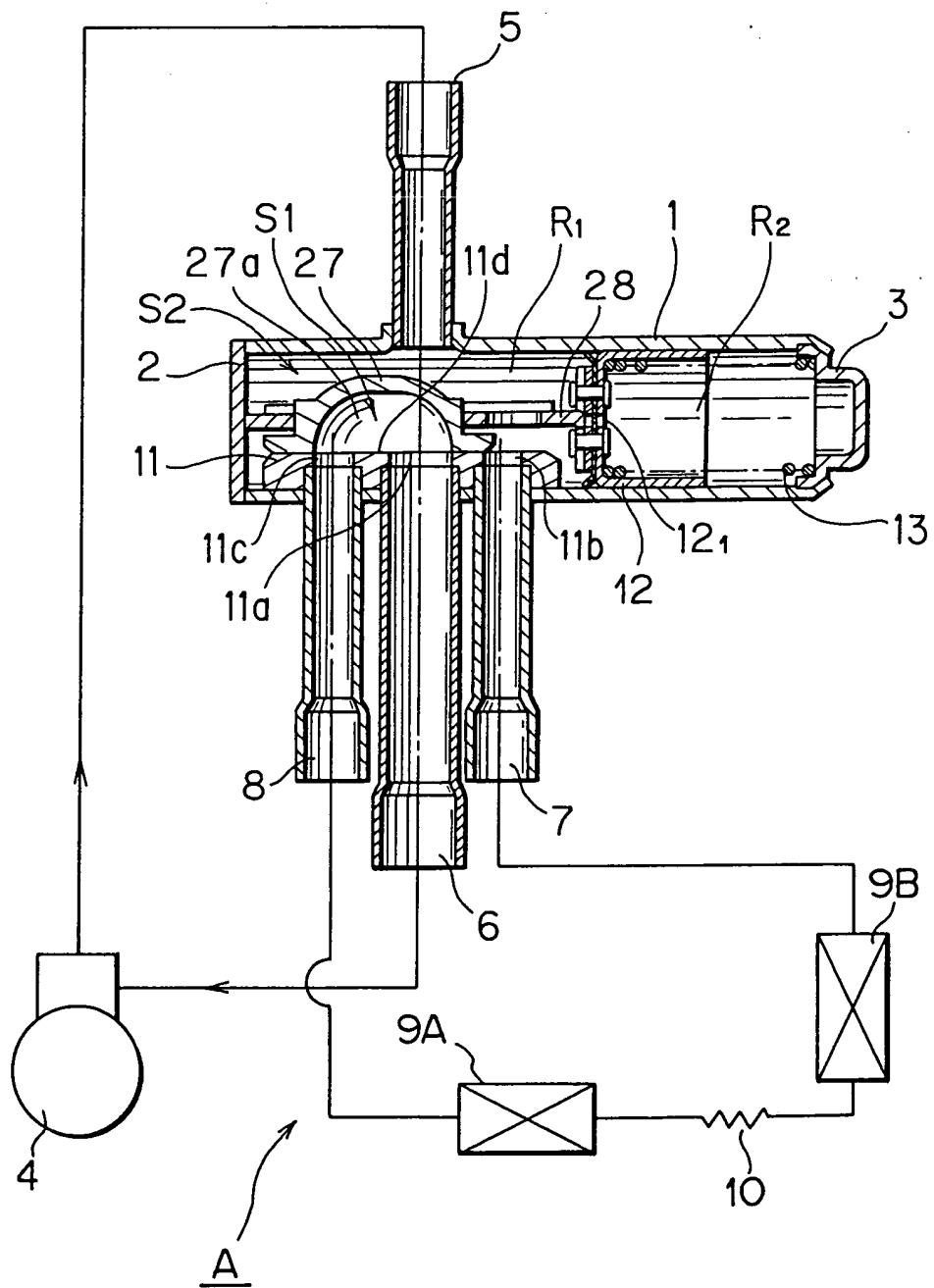


FIG. 8

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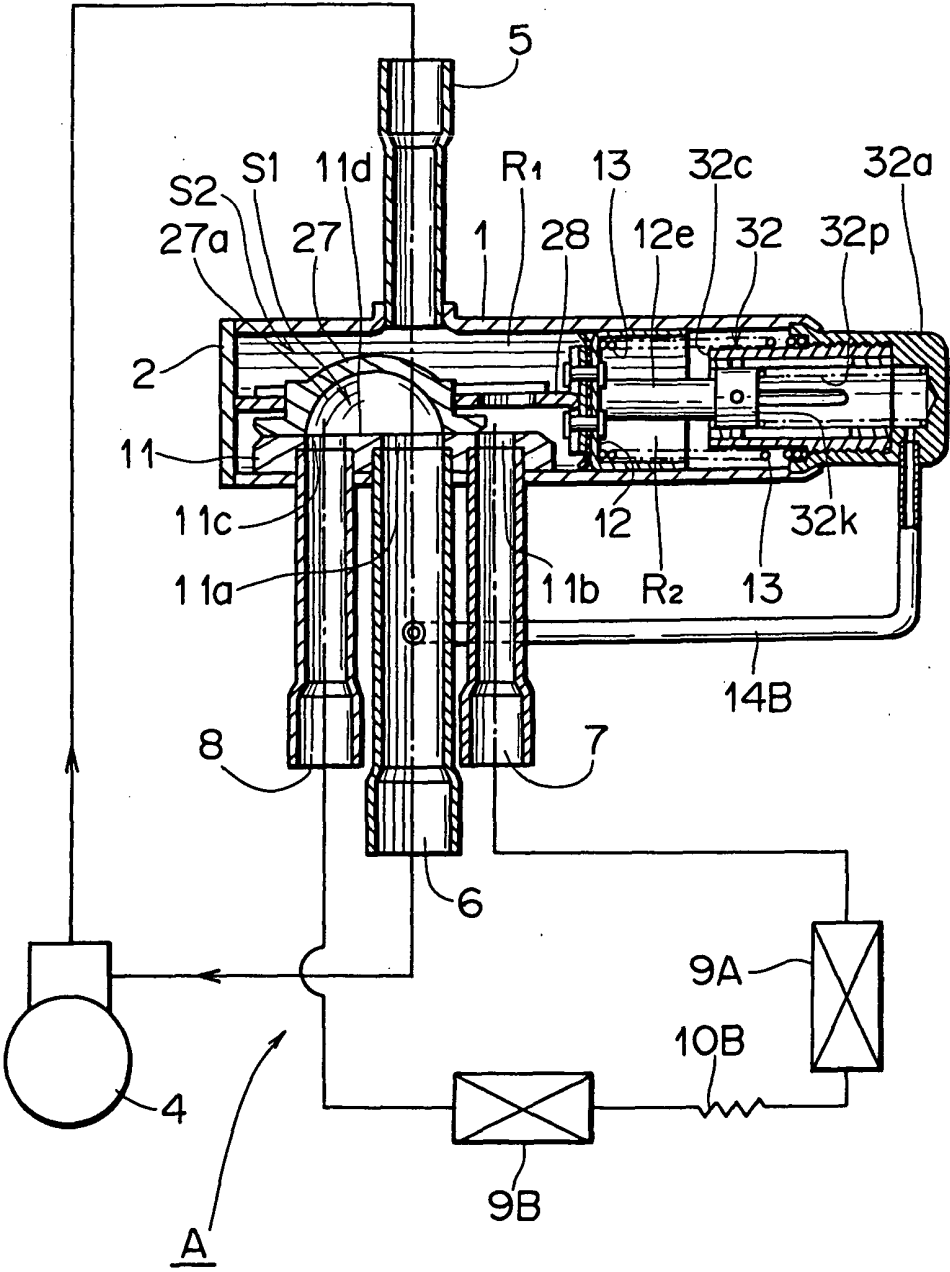


FIG. 9



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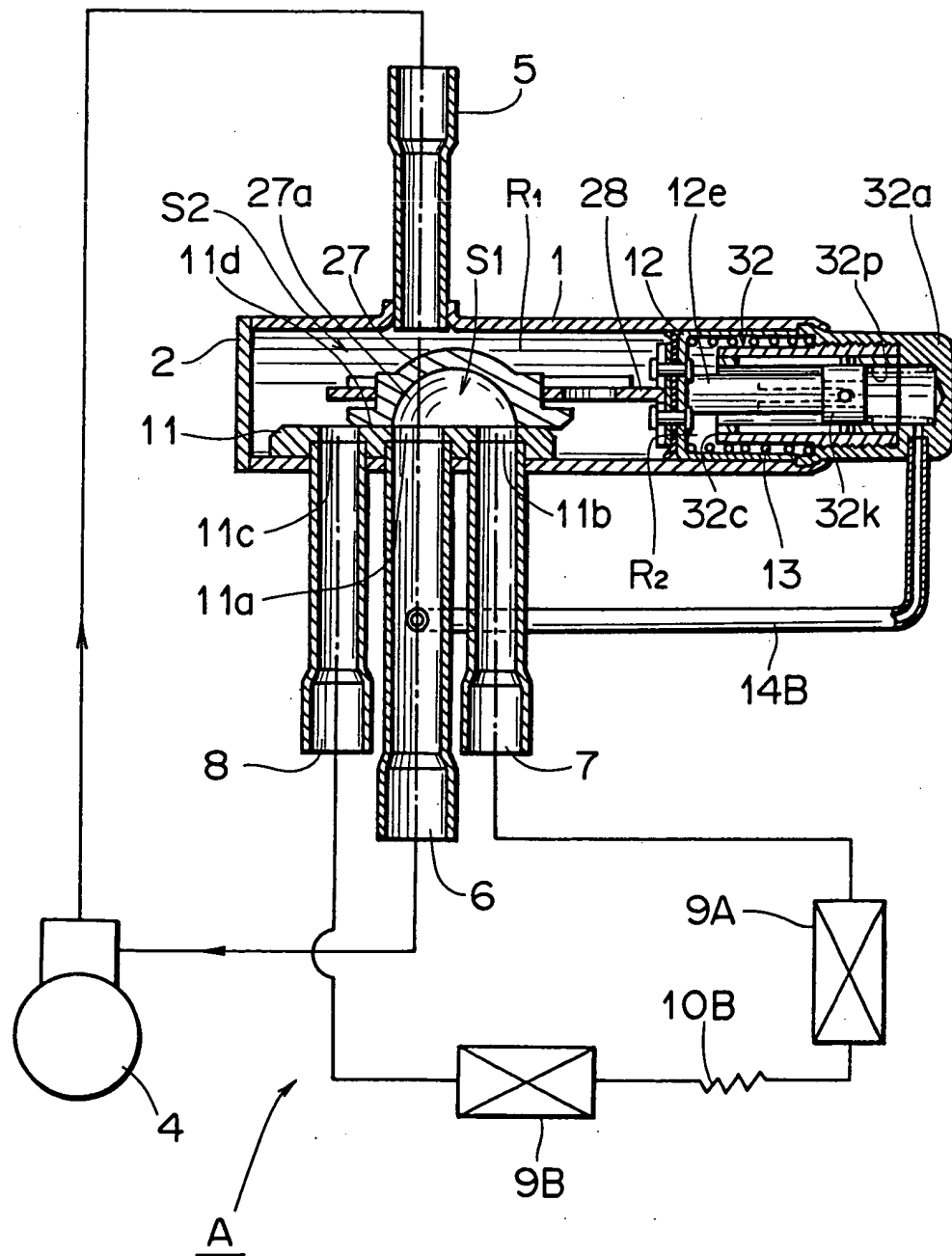
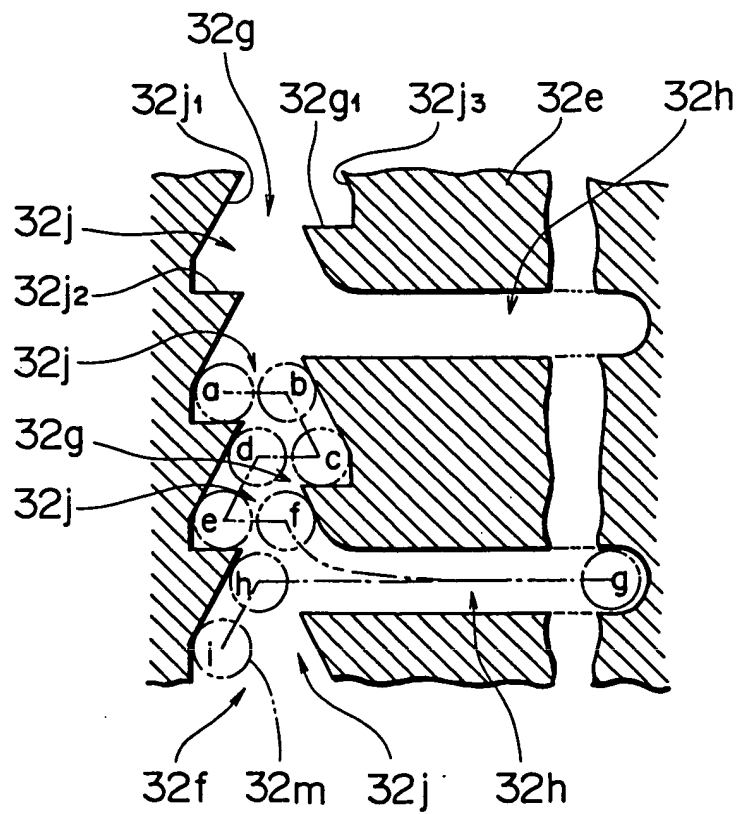
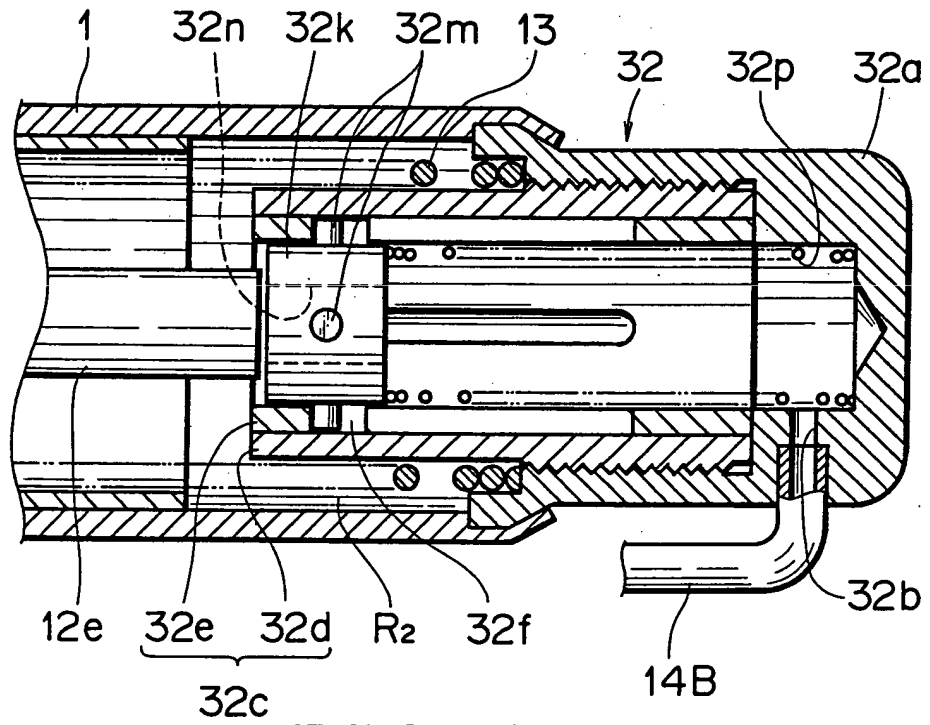


FIG. 10

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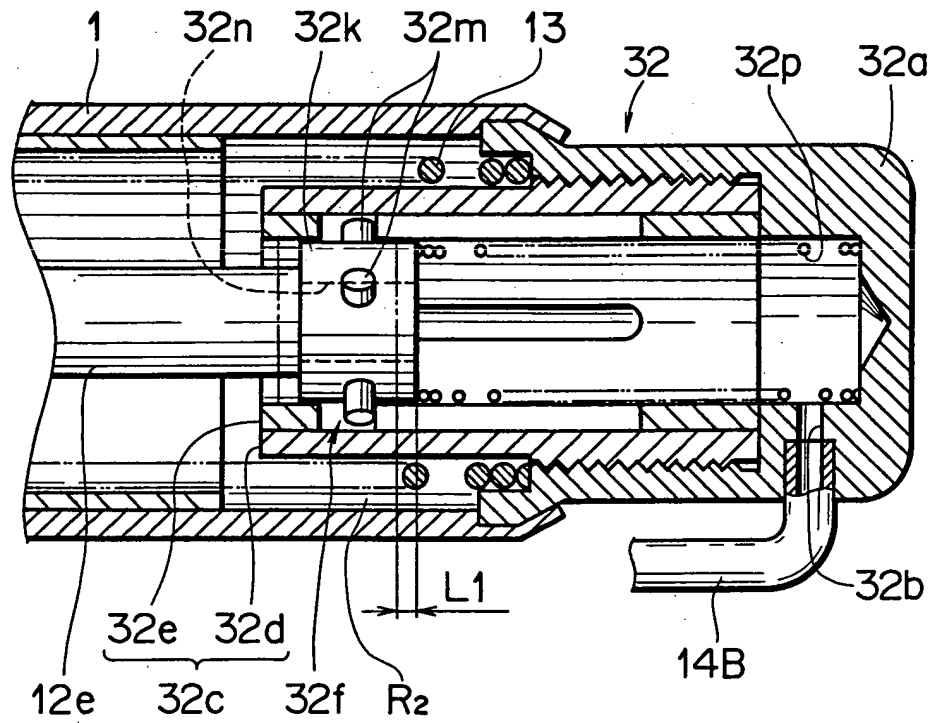


FIG. 13

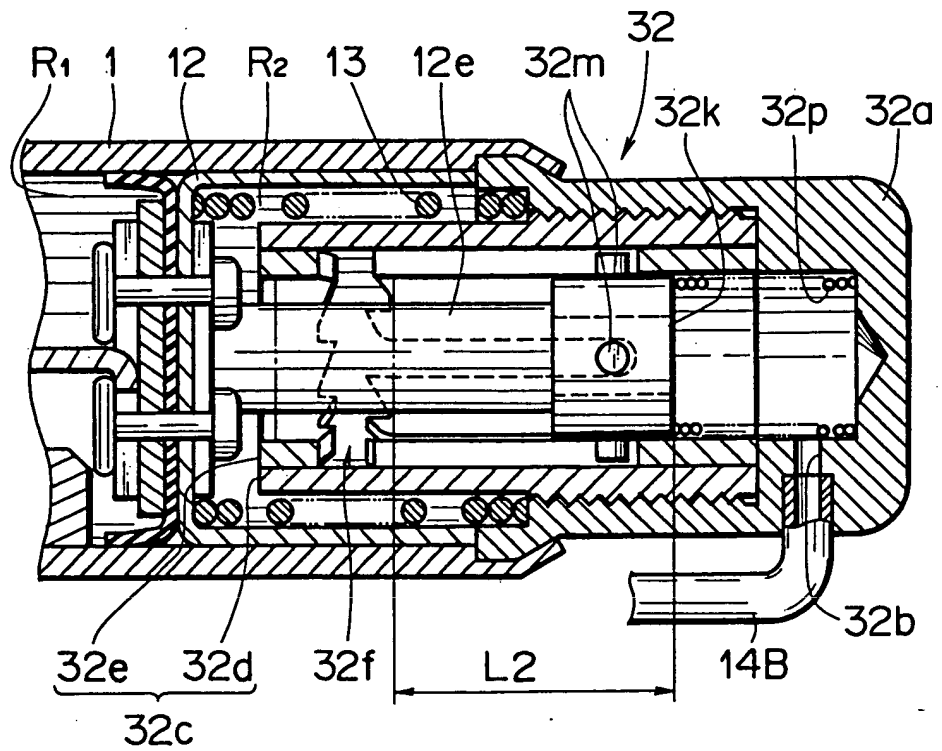


FIG. 14

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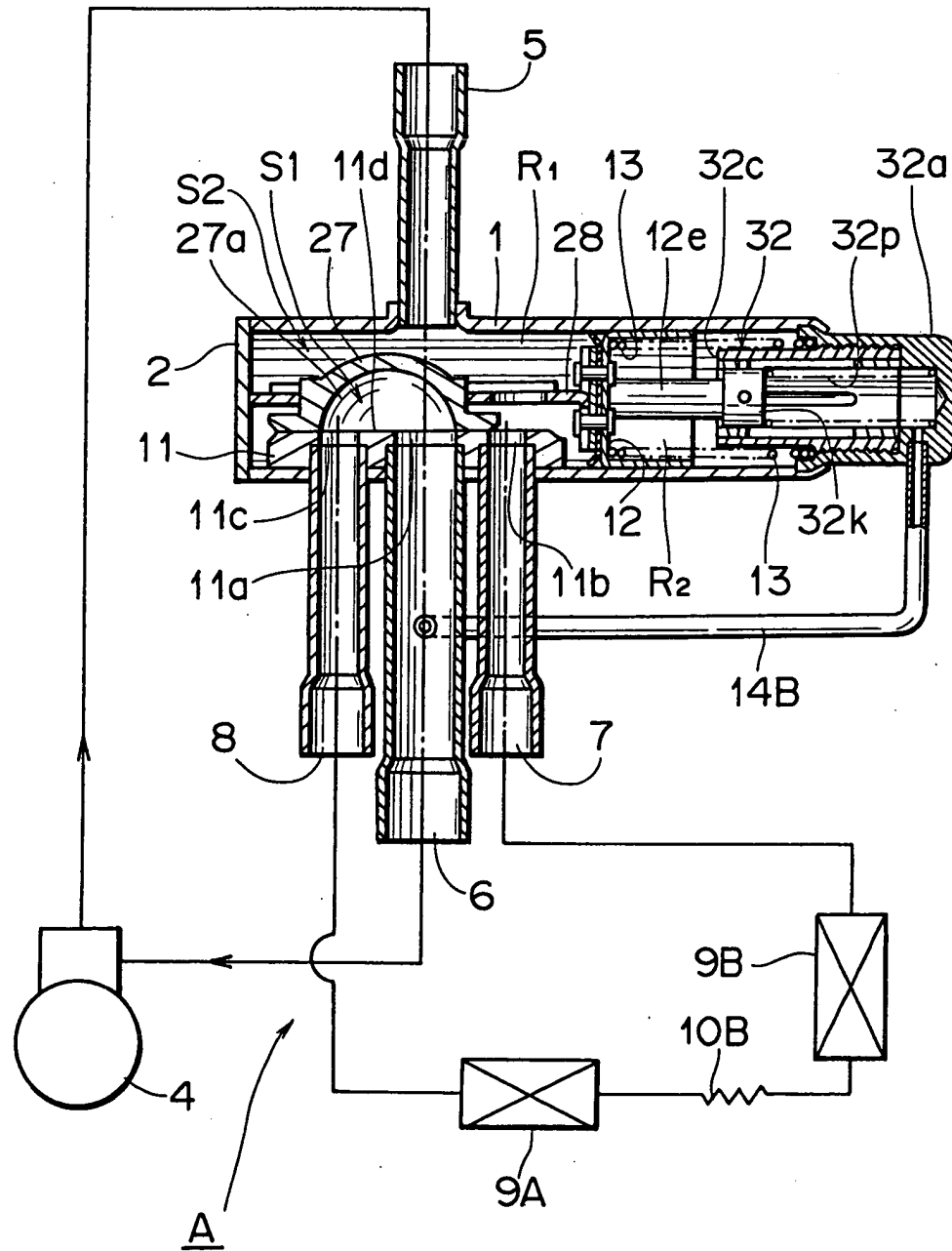


FIG. 15

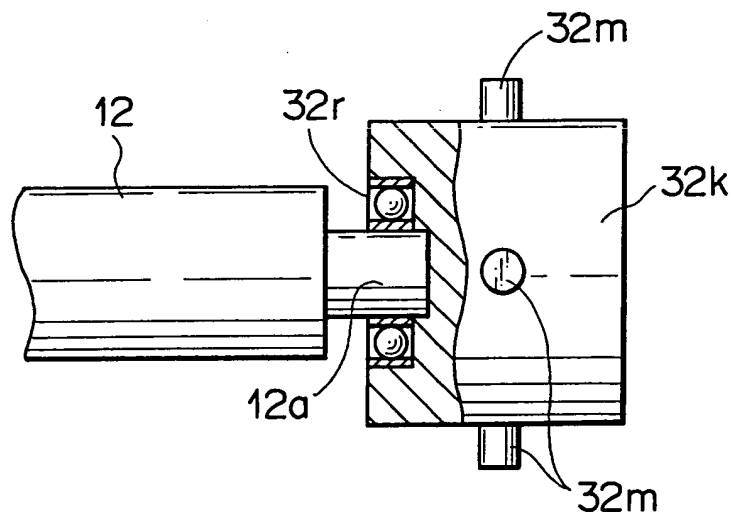


FIG. 16

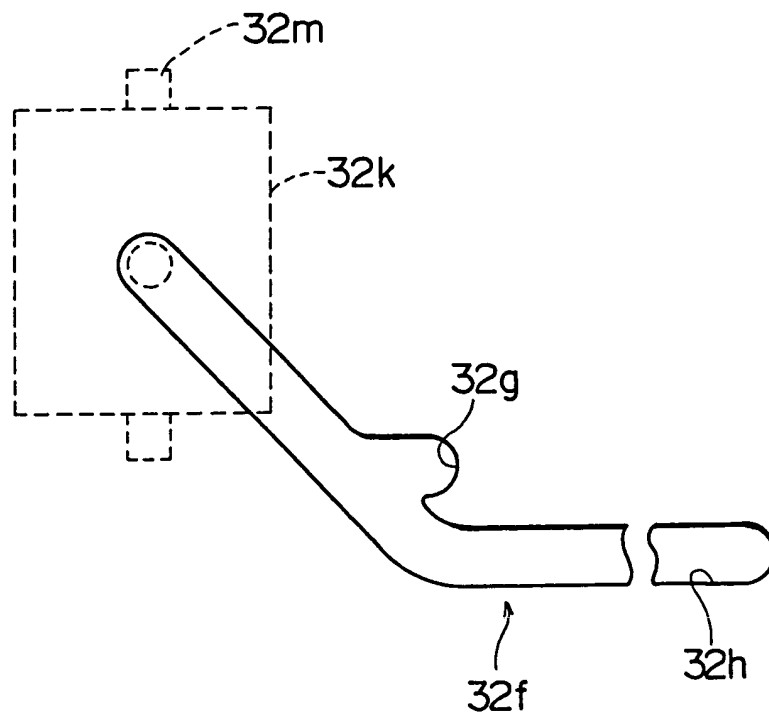


FIG. 17

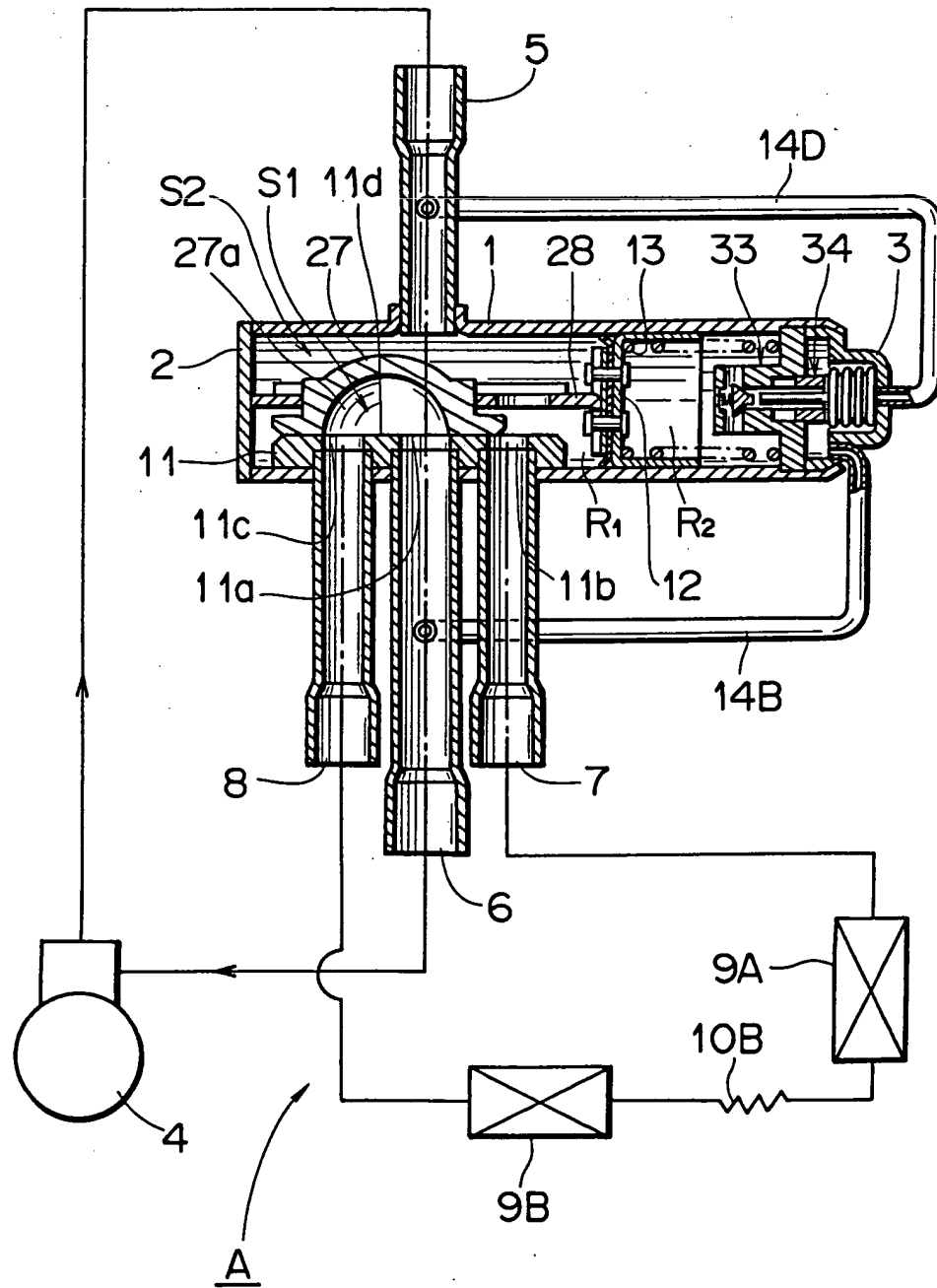
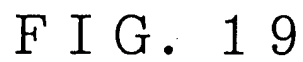


FIG. 18



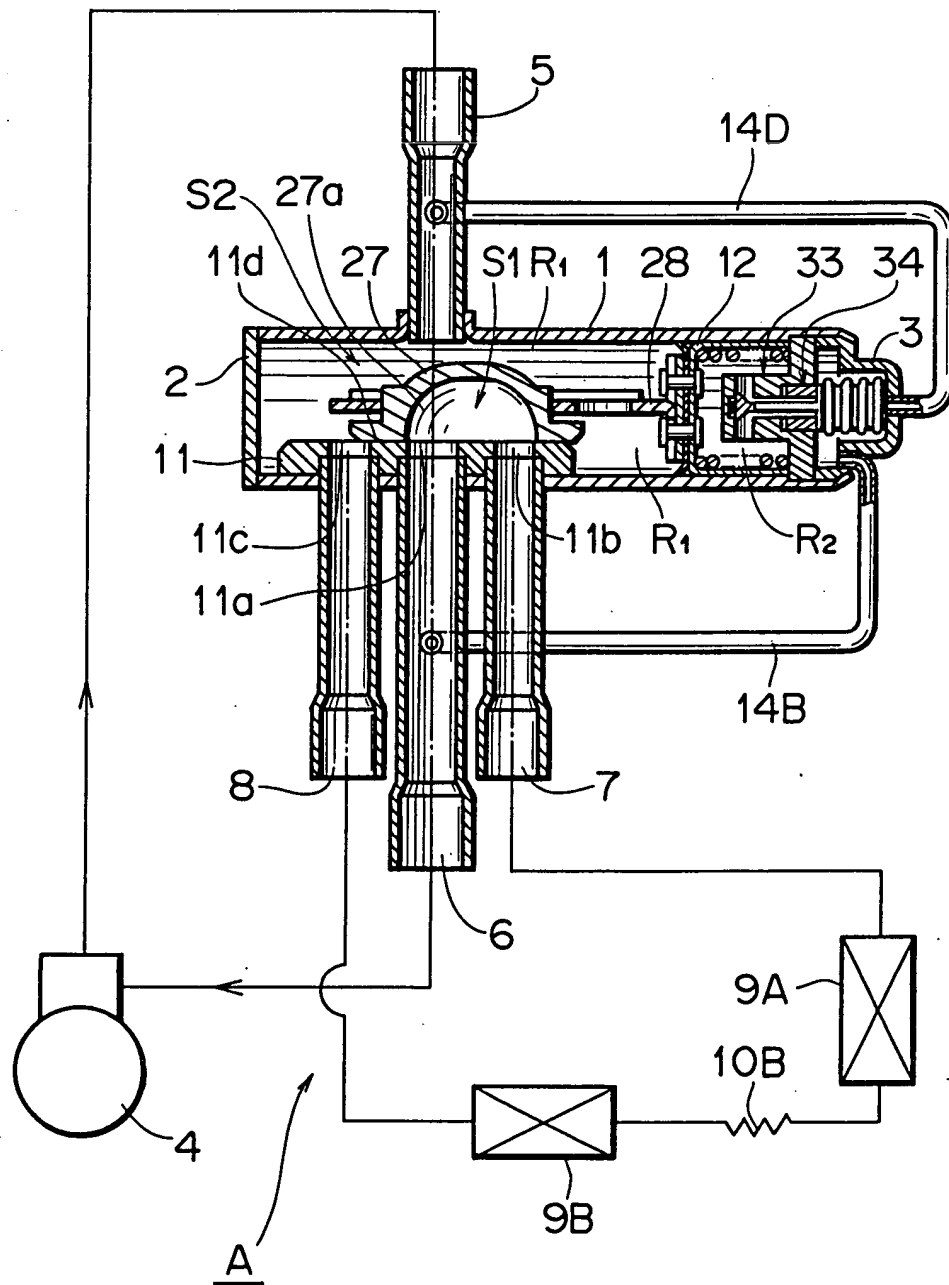


FIG. 22



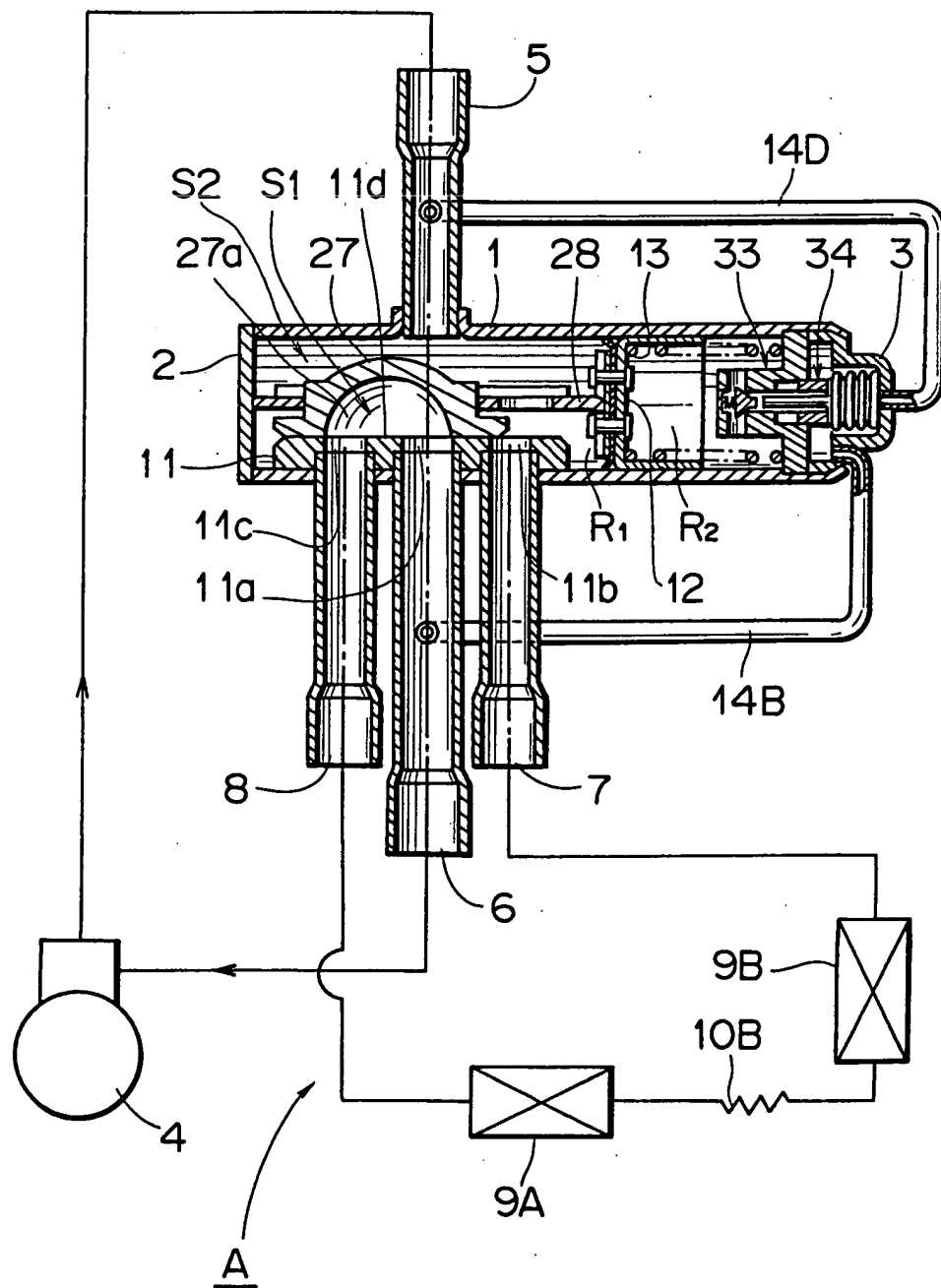


FIG. 23

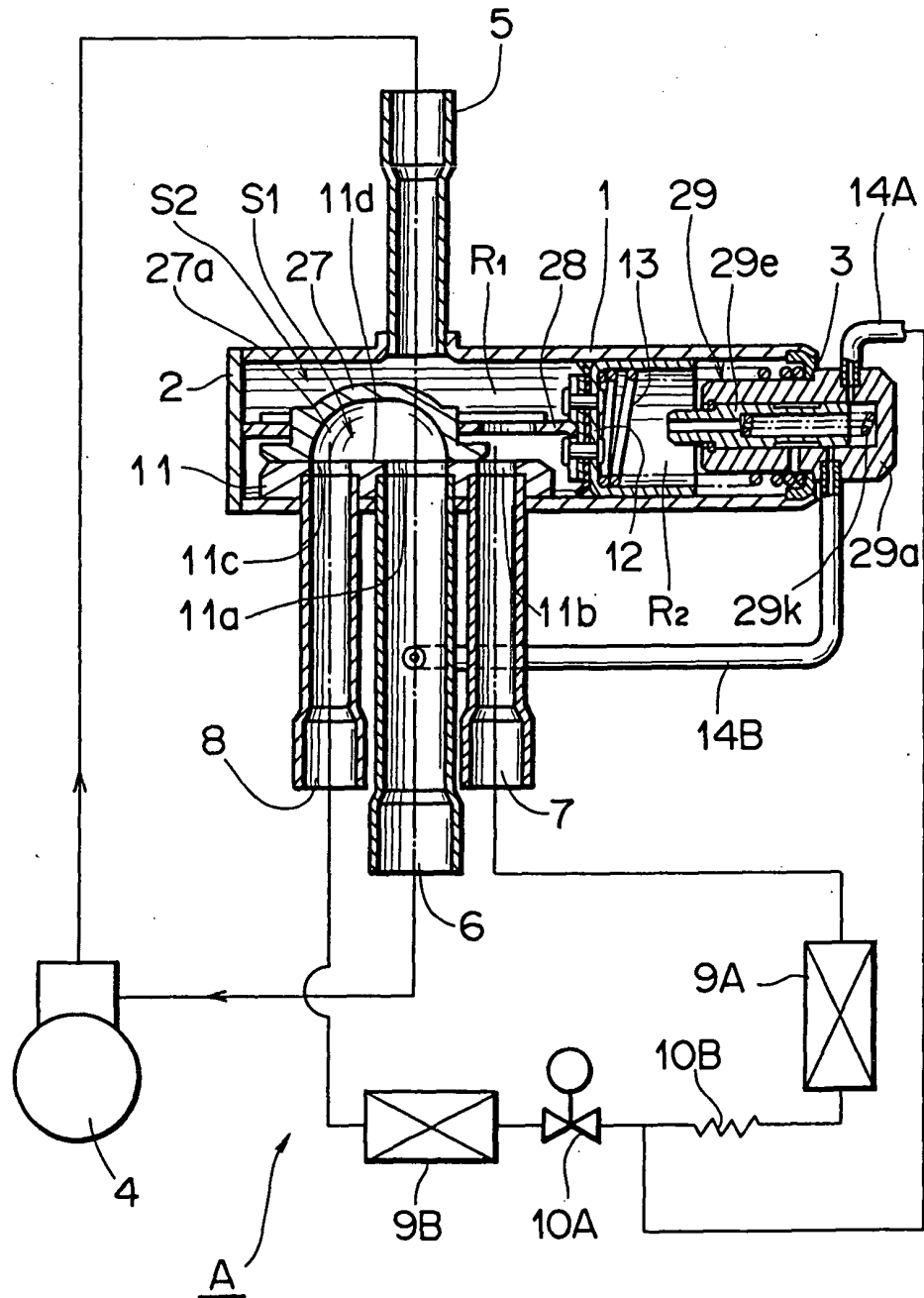


FIG. 24

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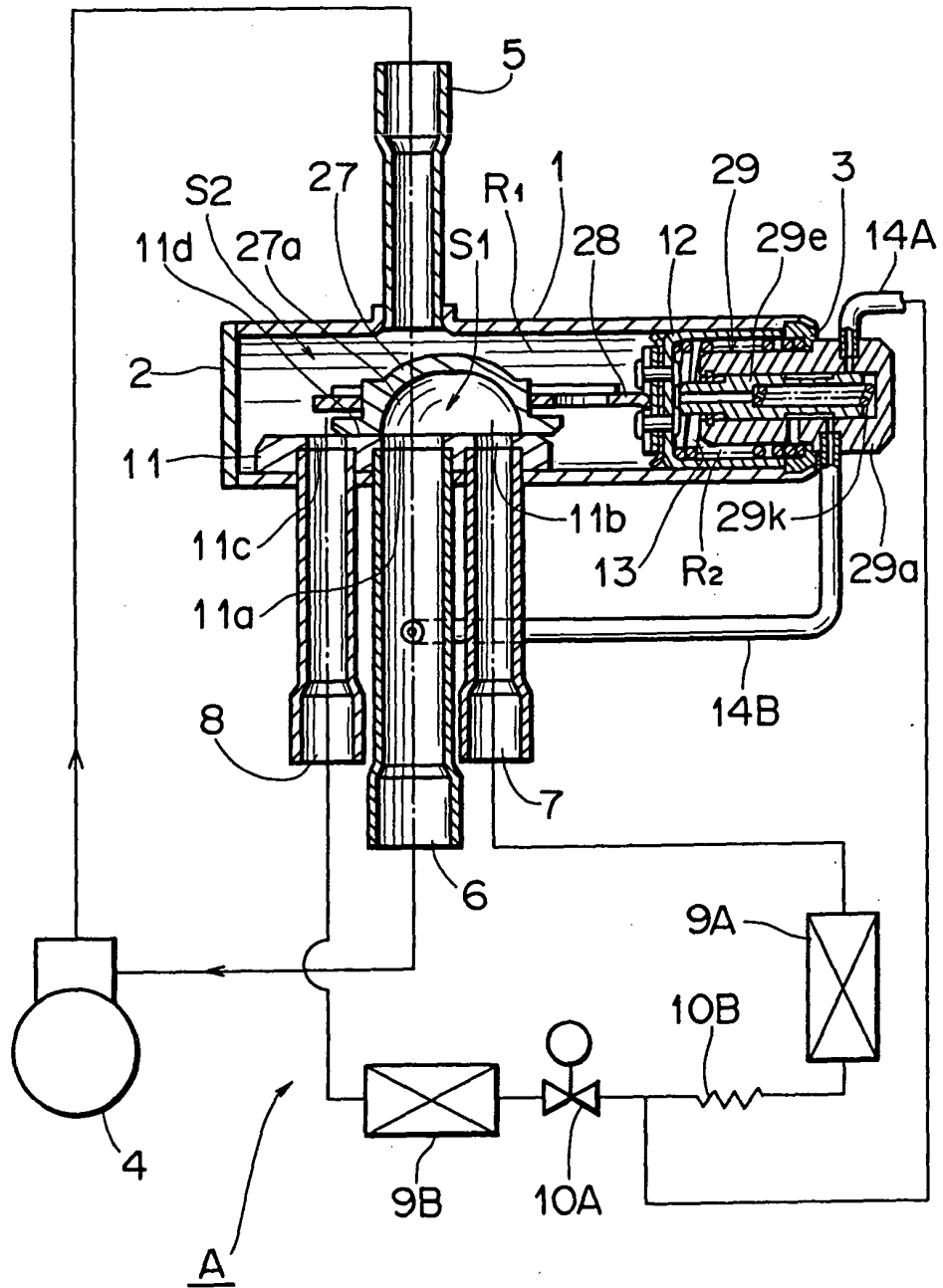


FIG. 25

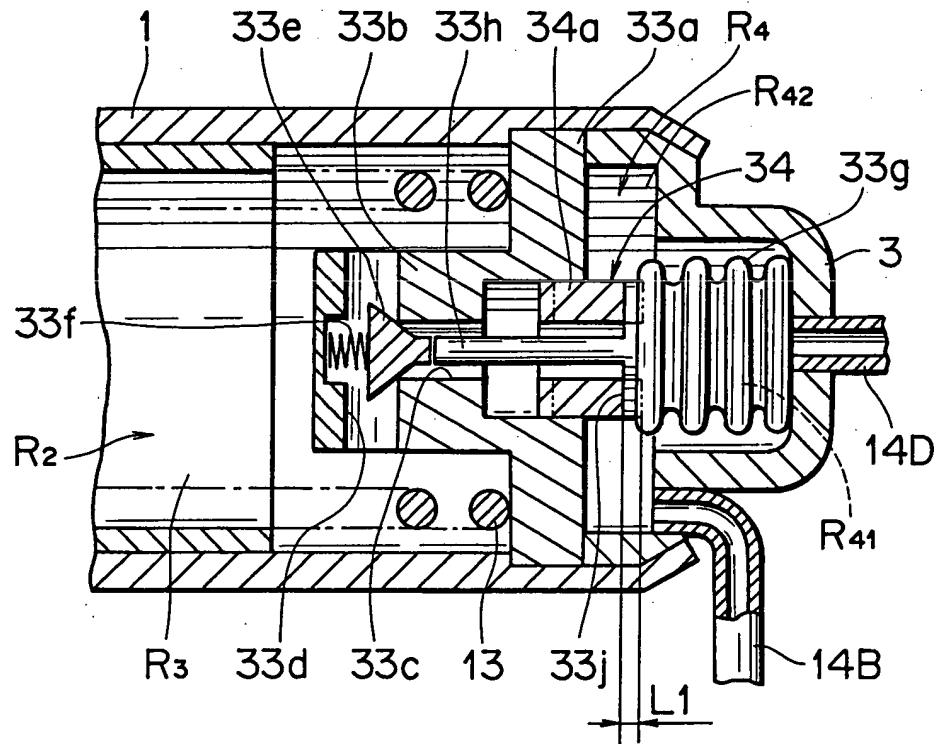


FIG. 21

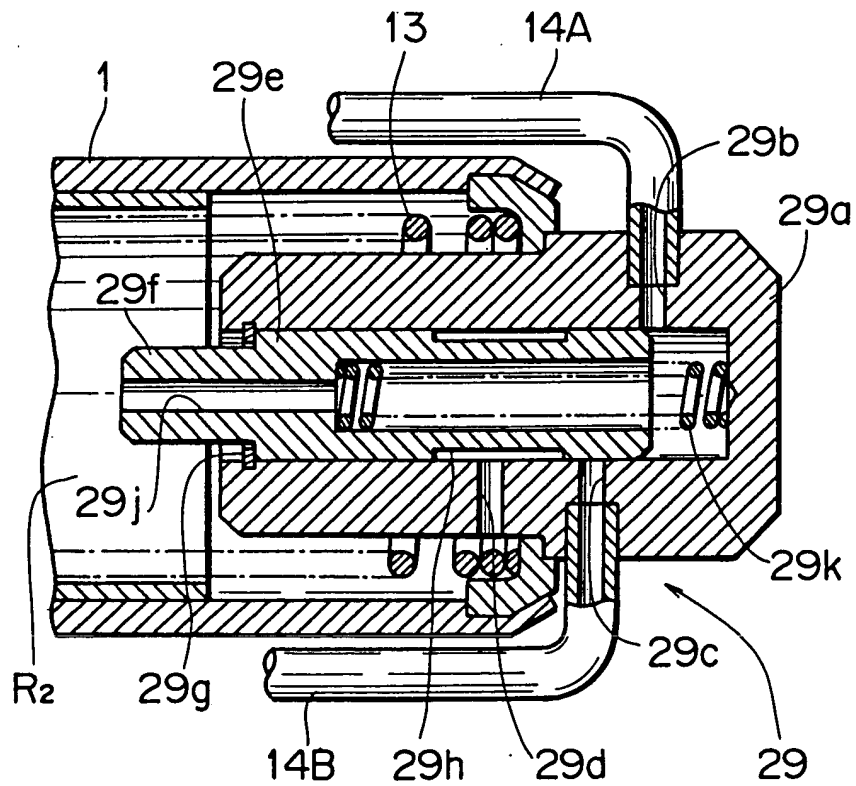
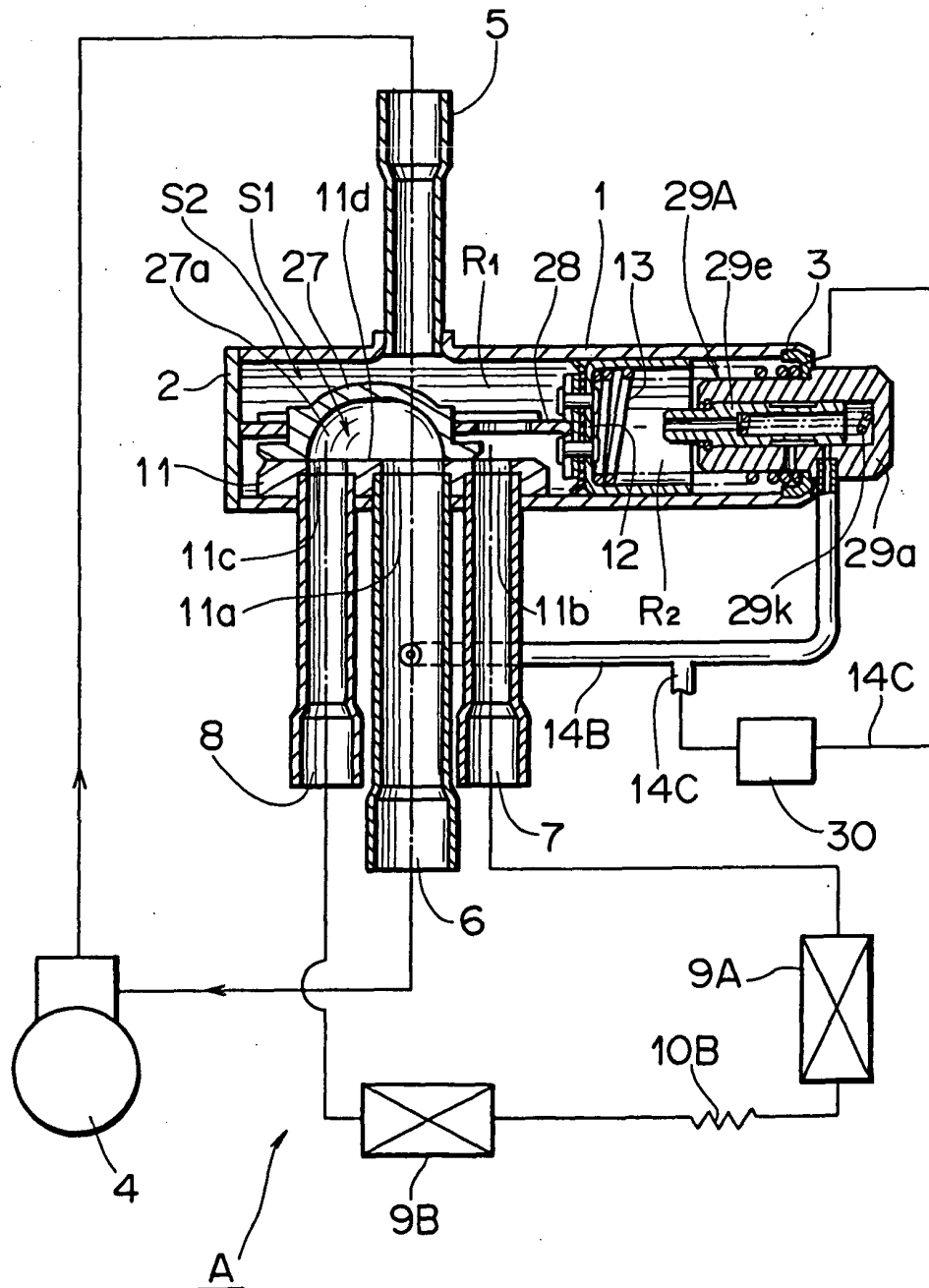


FIG. 26



A cross-sectional view of a semiconductor device 30. The device features a central substrate 30d with a diagonal hatching pattern. This substrate is surrounded by a frame-like structure 30a. On the left and right sides, there are protruding structures 14C. Various layers and features are labeled: 30j (top surface), 30a (top frame), 30c (left side frame), 30b (right side frame), 30f (bottom frame), 30h (bottom surface), 30e (bottom frame), 30j (bottom surface), 30g (bottom frame), and 30d (central substrate). The device is shown in a cross-section with hatching indicating different materials or layers.

FIG. 29

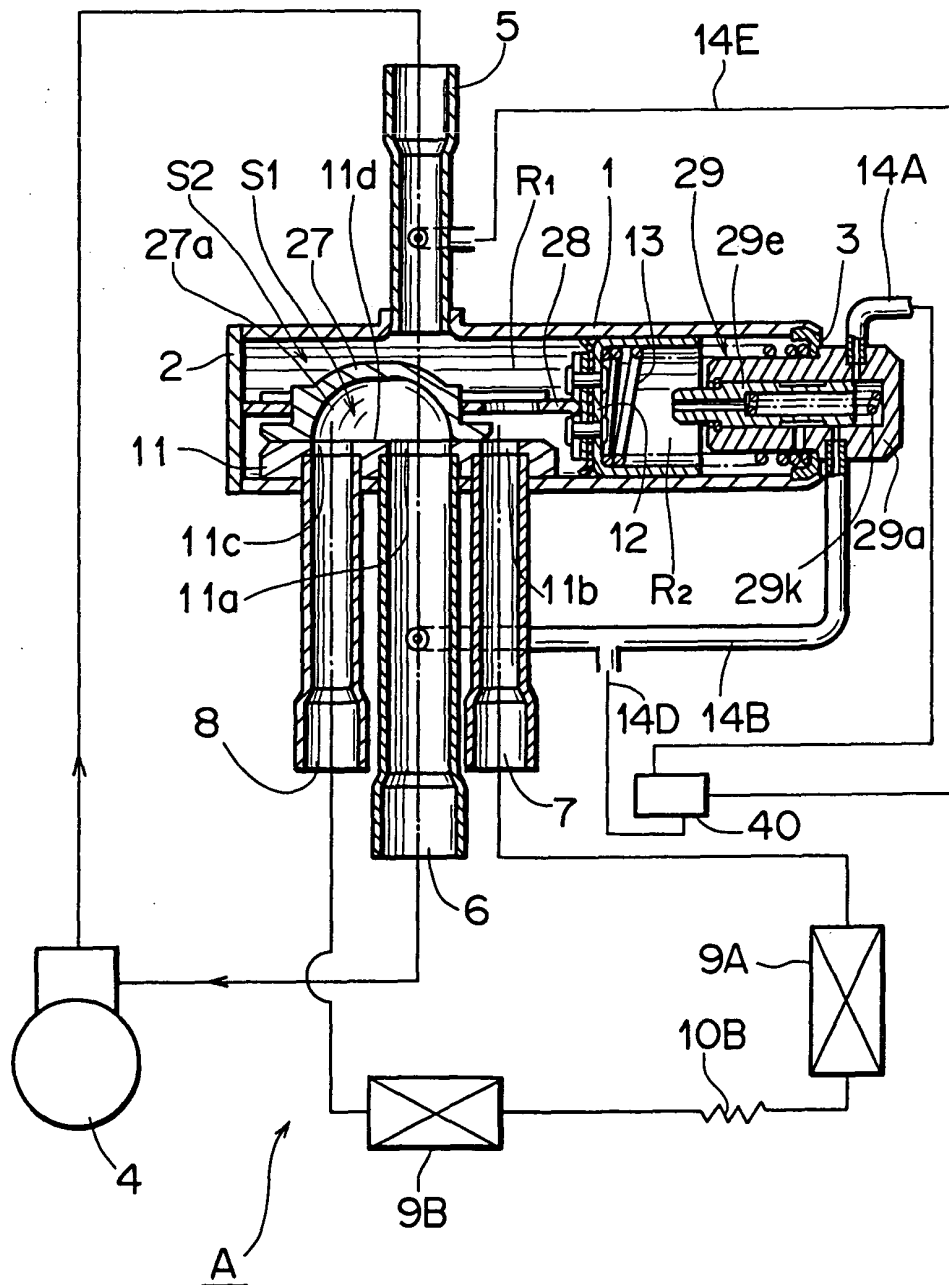


FIG. 30

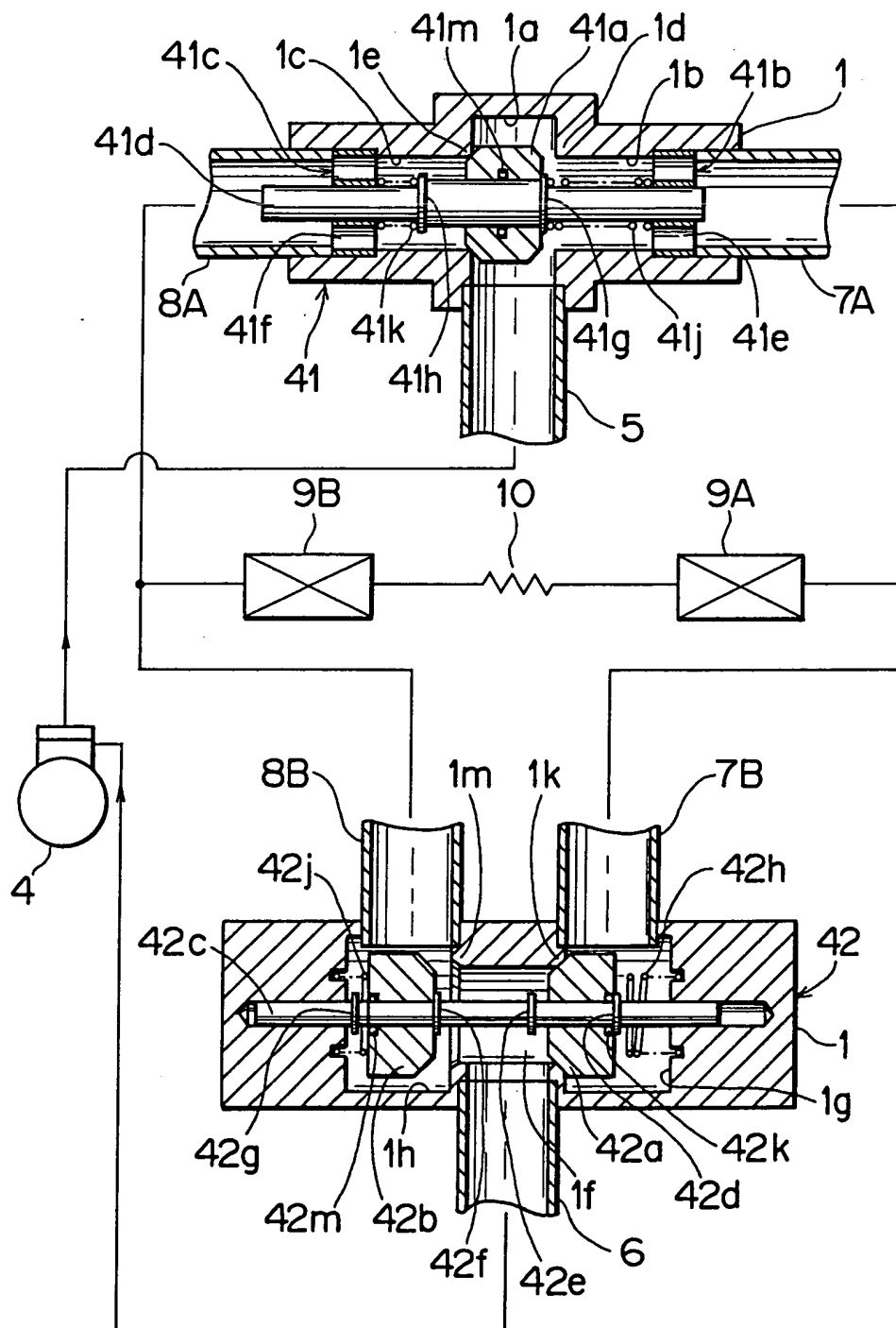


FIG. 32



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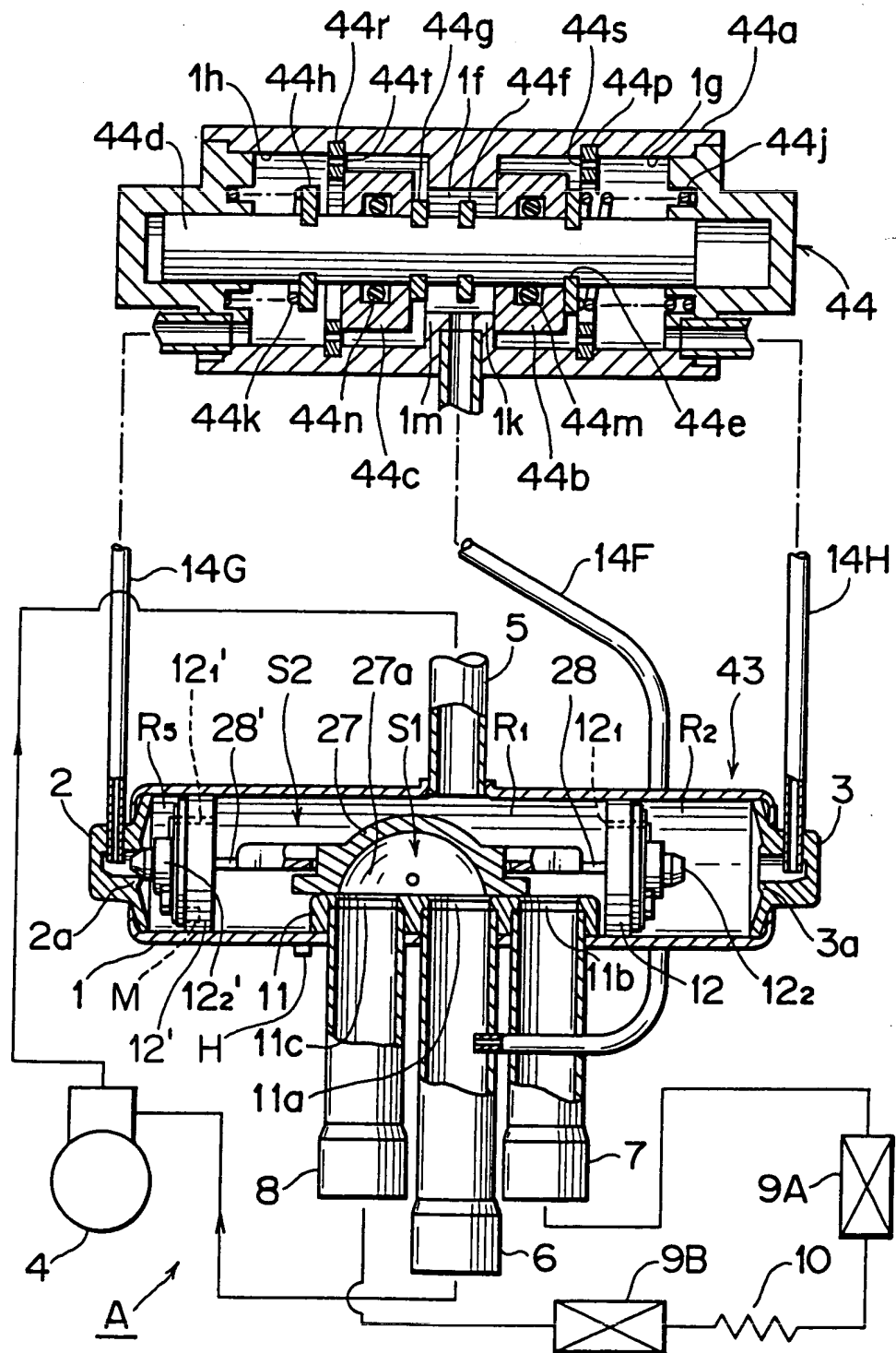


FIG. 33

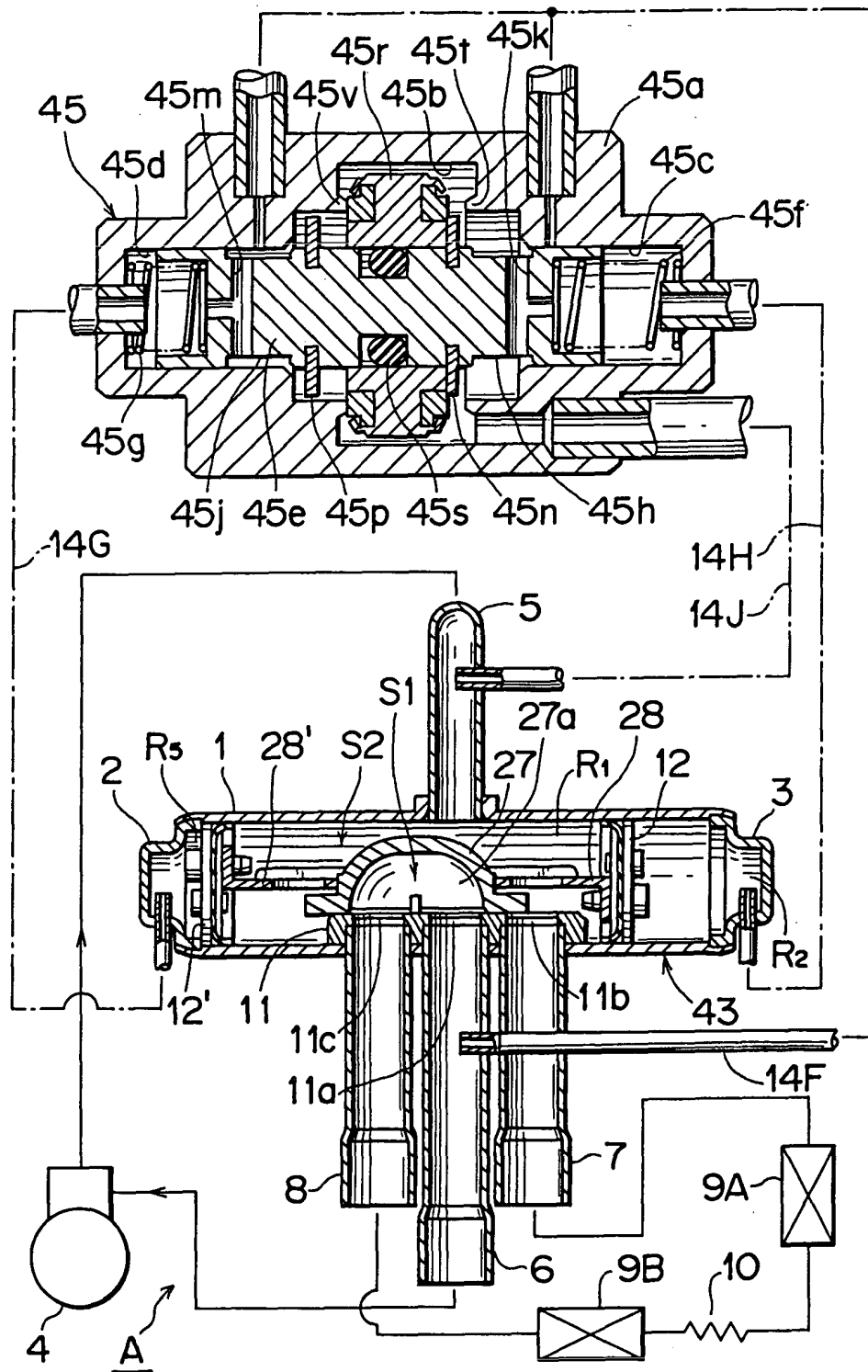


FIG. 34

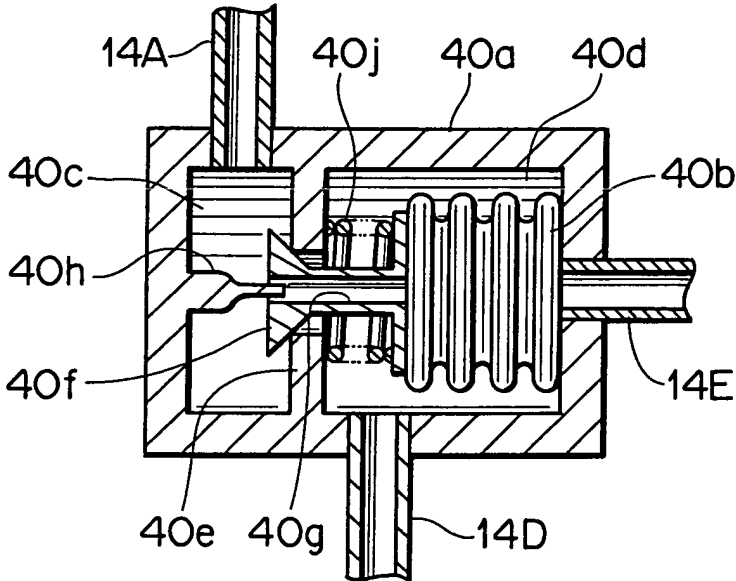


FIG. 31

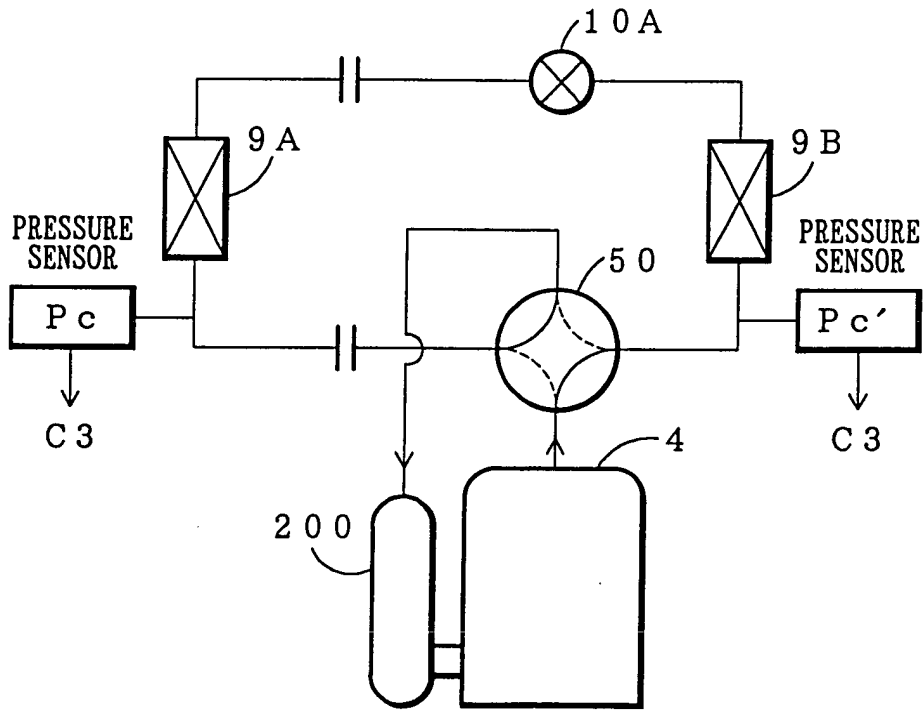


FIG. 35

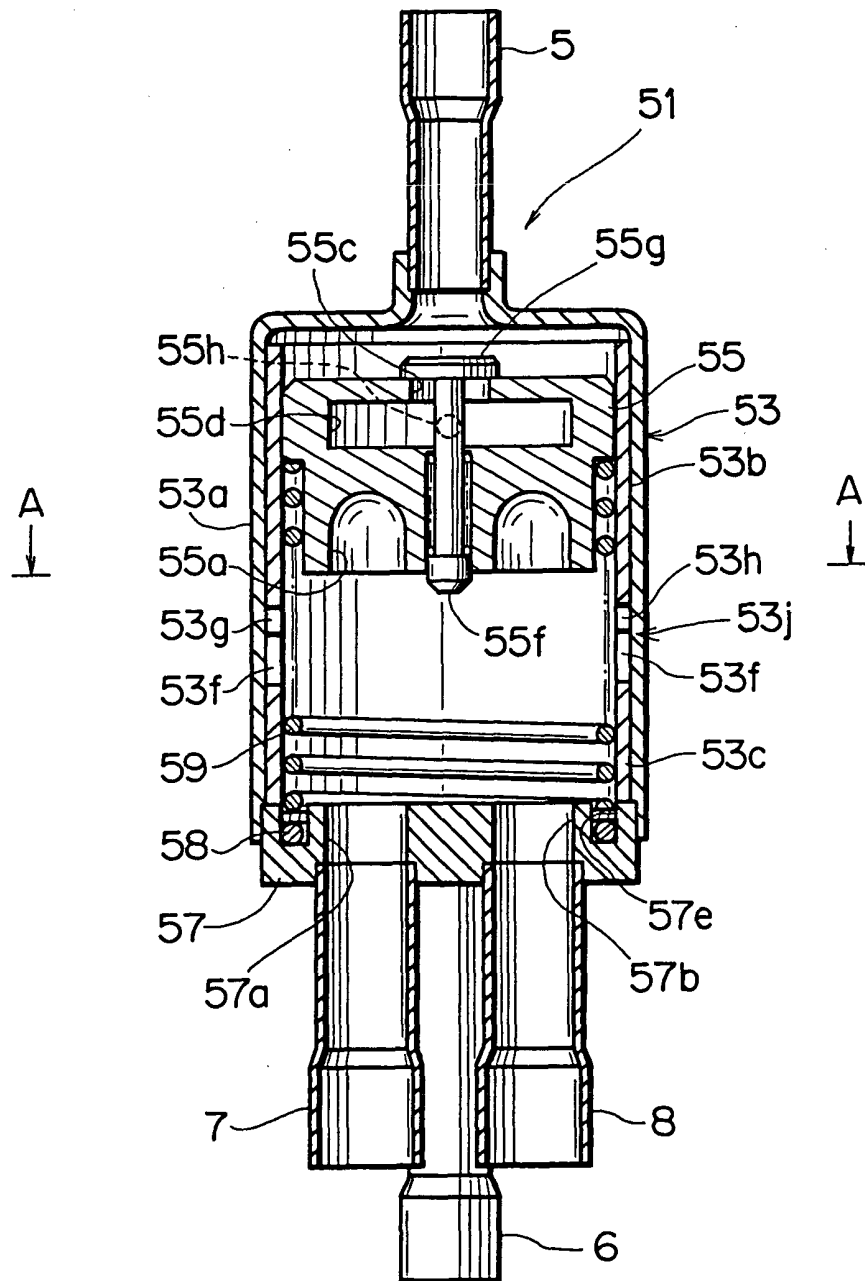


FIG. 36

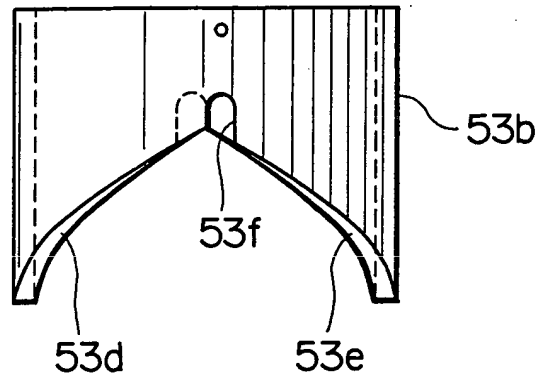


FIG. 37

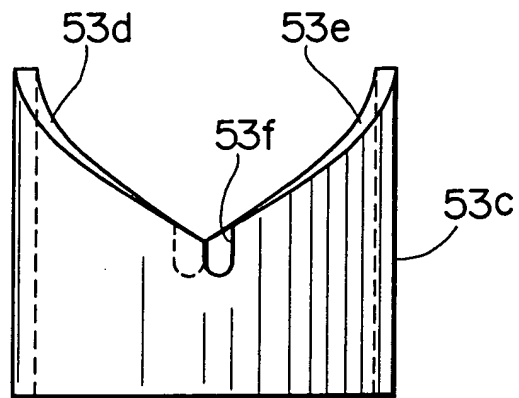


FIG. 38

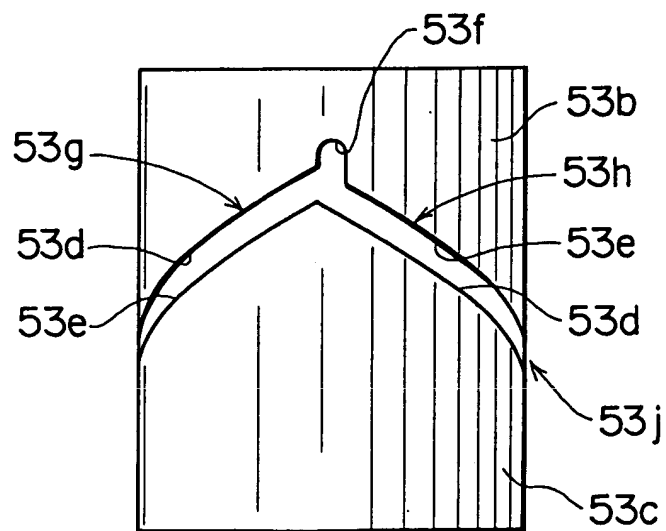


FIG. 39

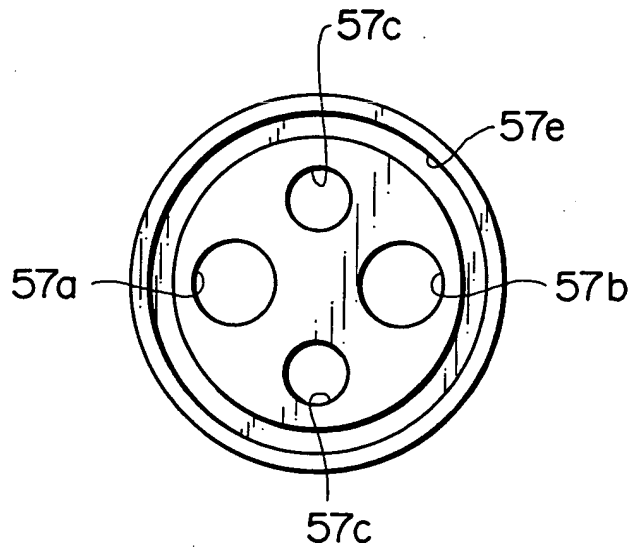


FIG. 40

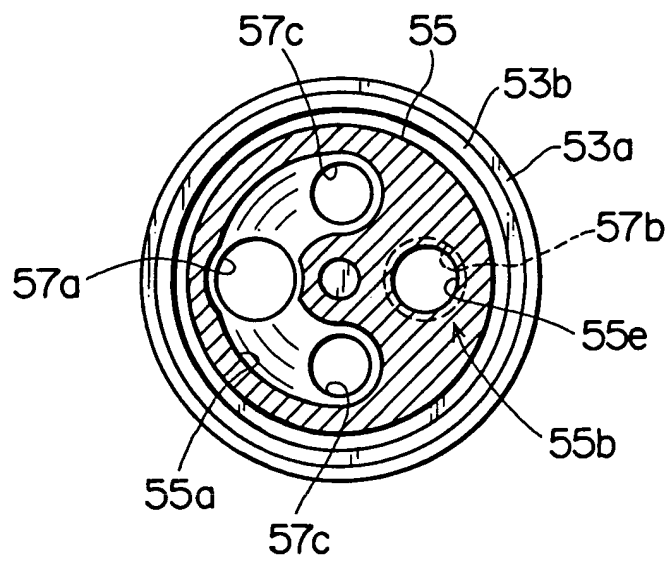


FIG. 41

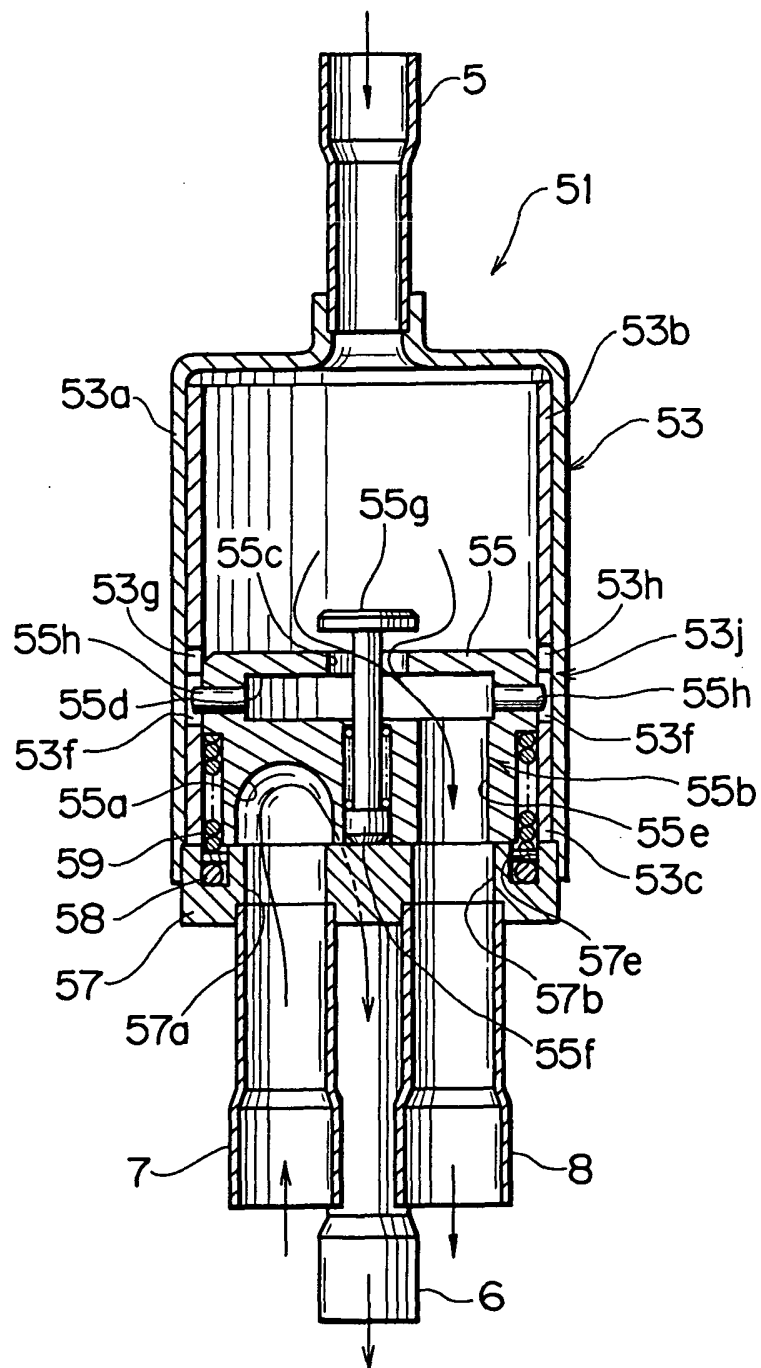


FIG. 42

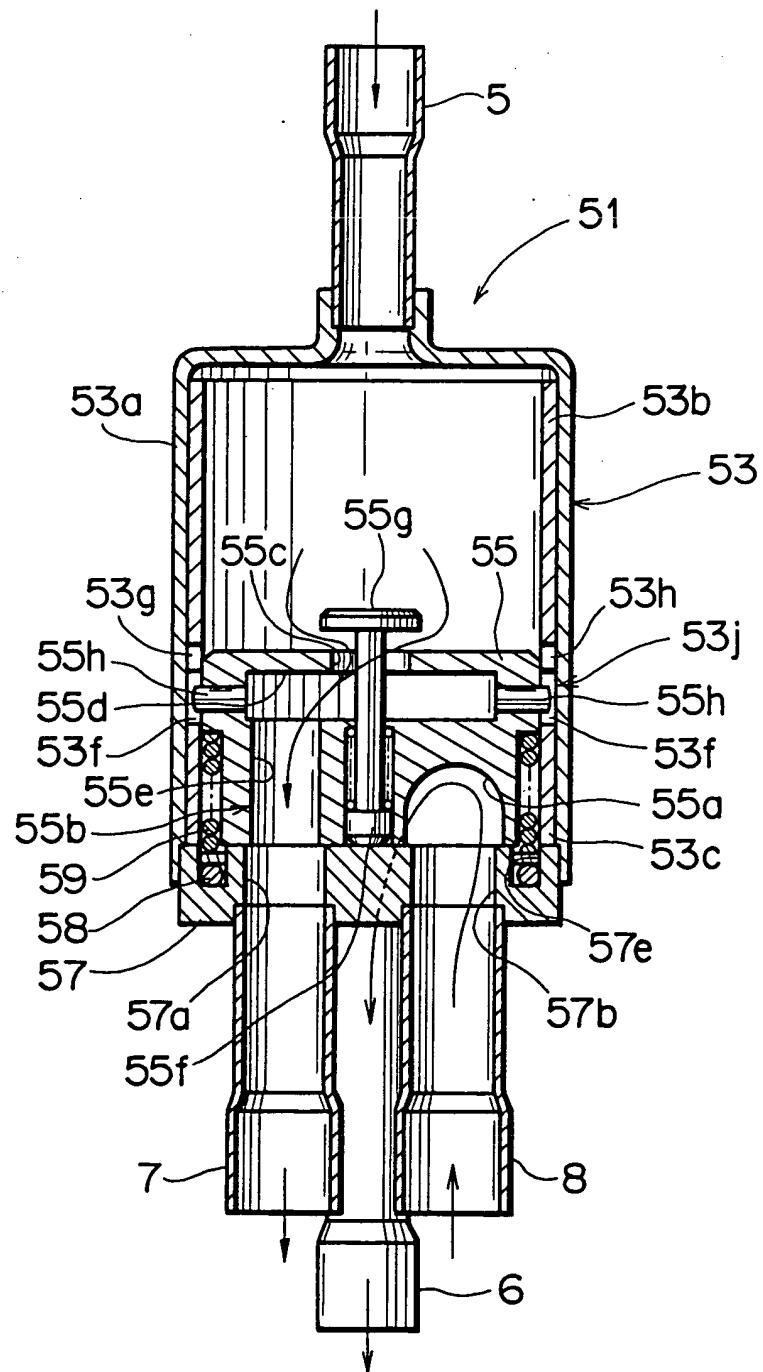


FIG. 43



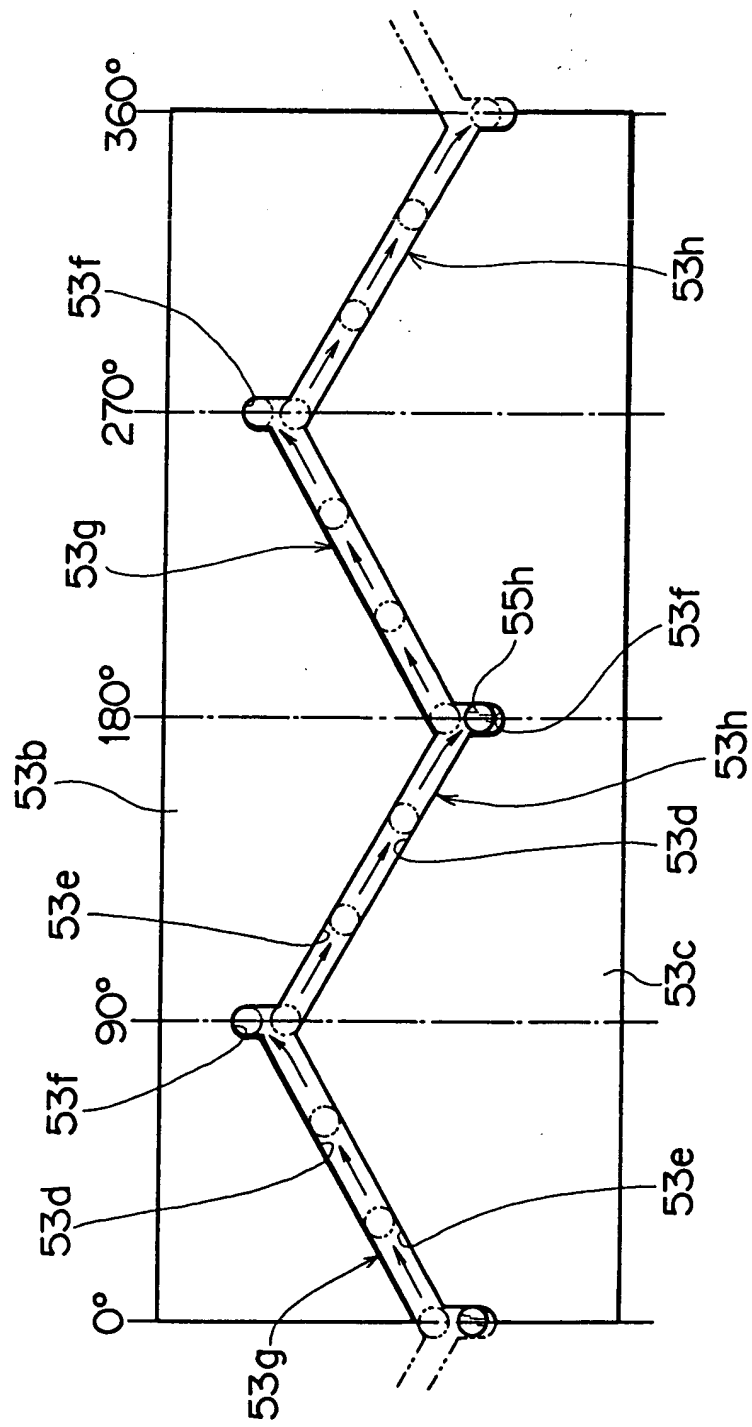


FIG. 44

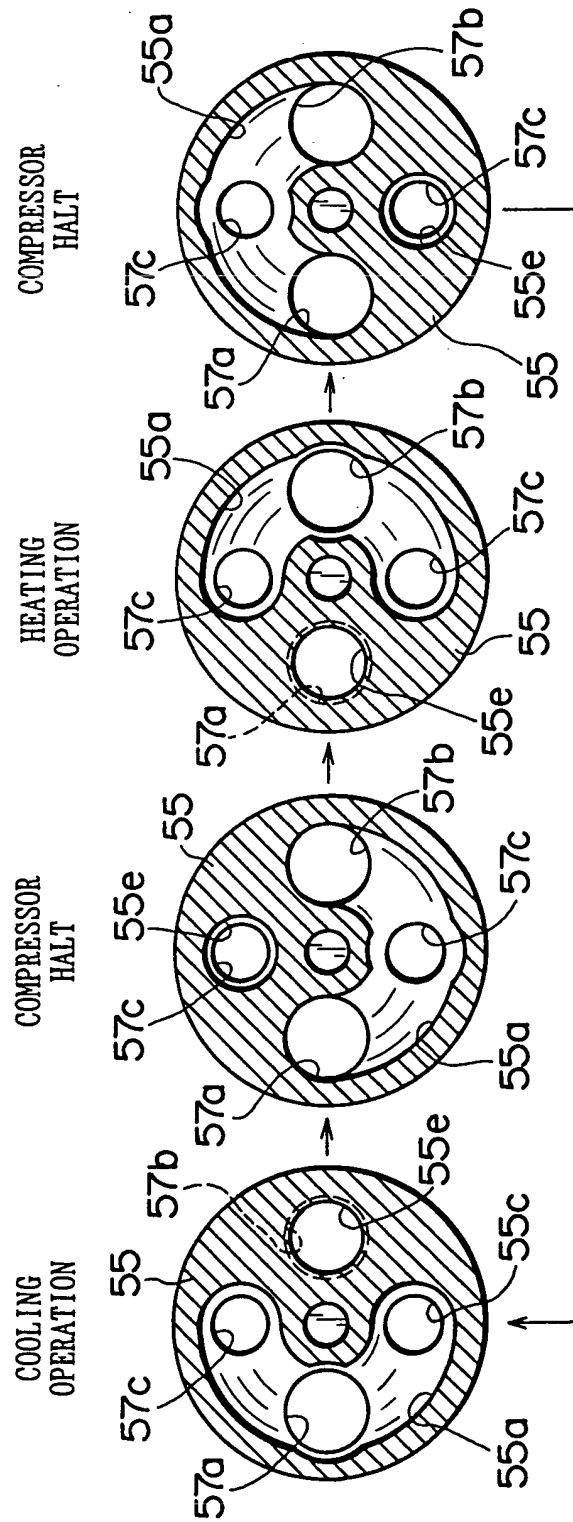


FIG. 45

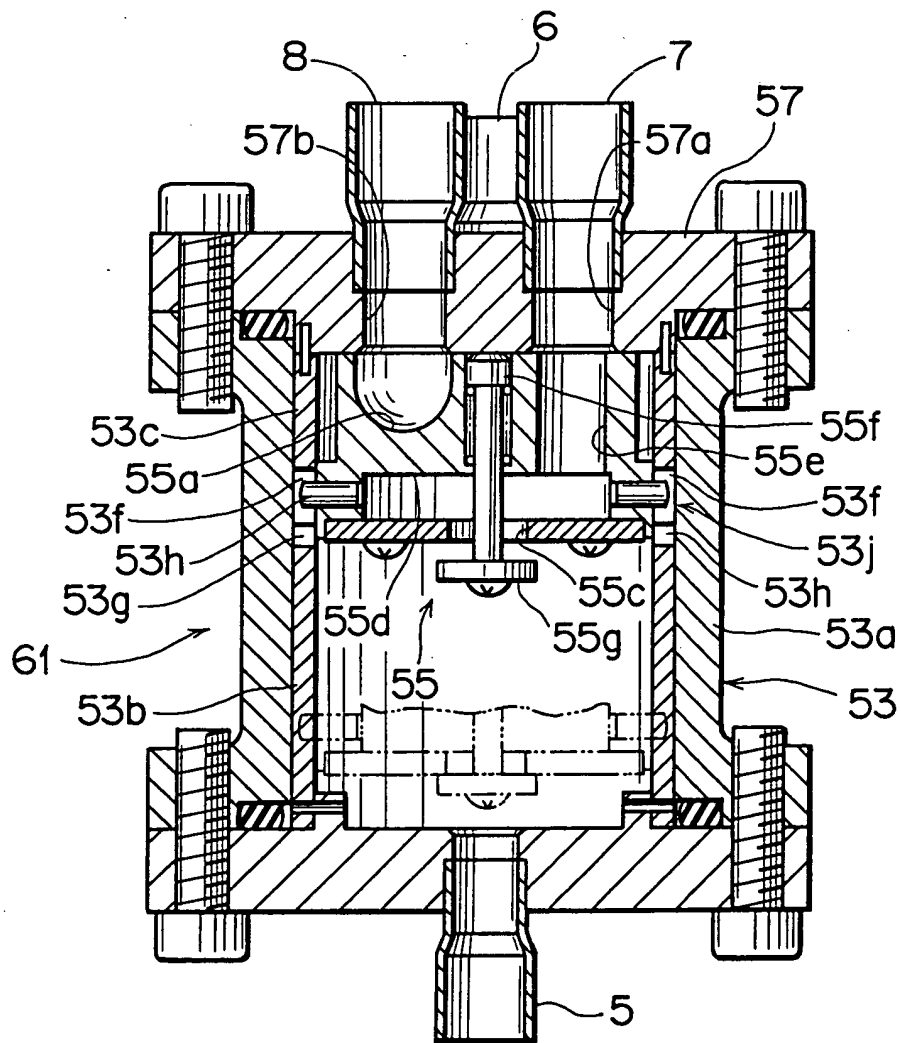


FIG. 46

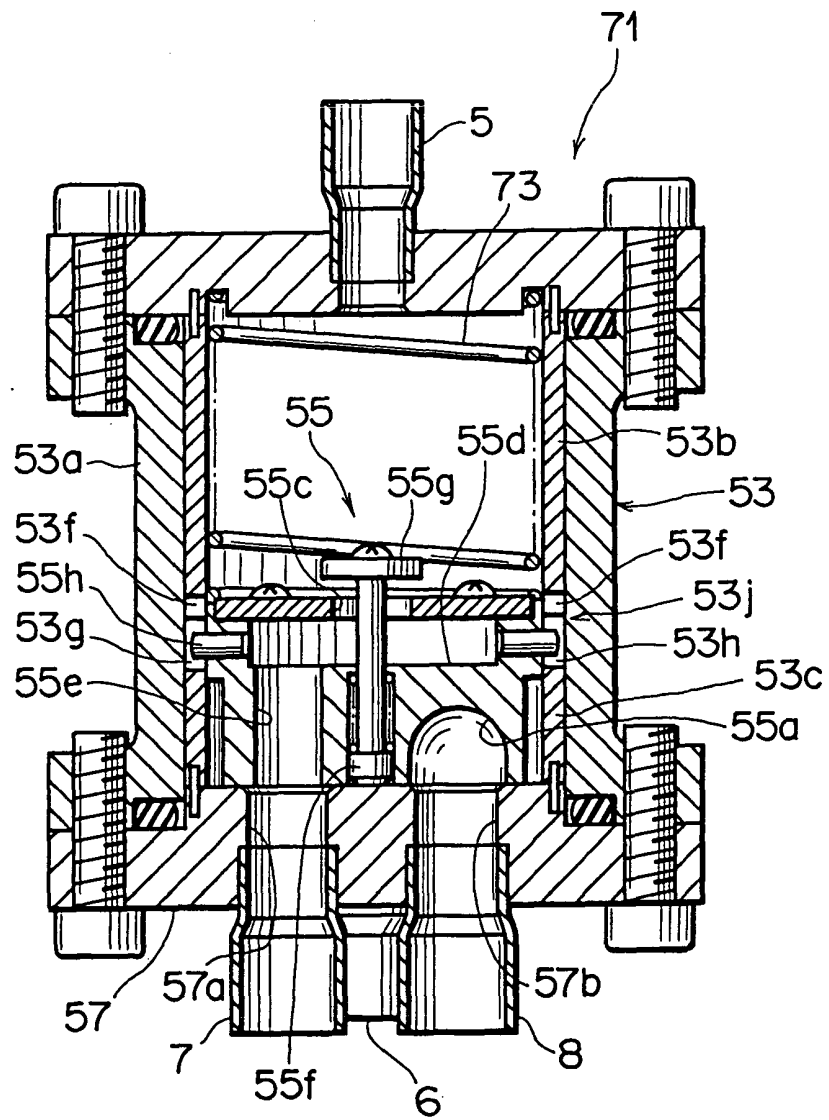


FIG. 47

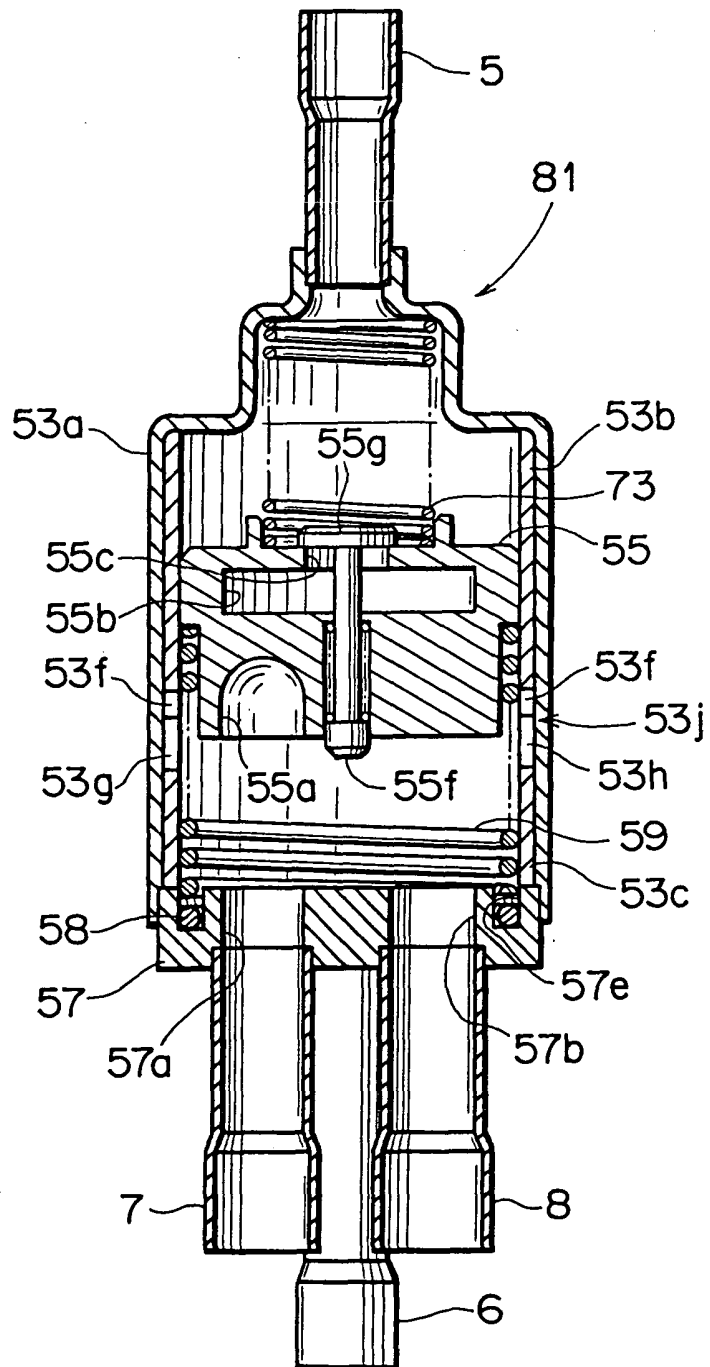


FIG. 48

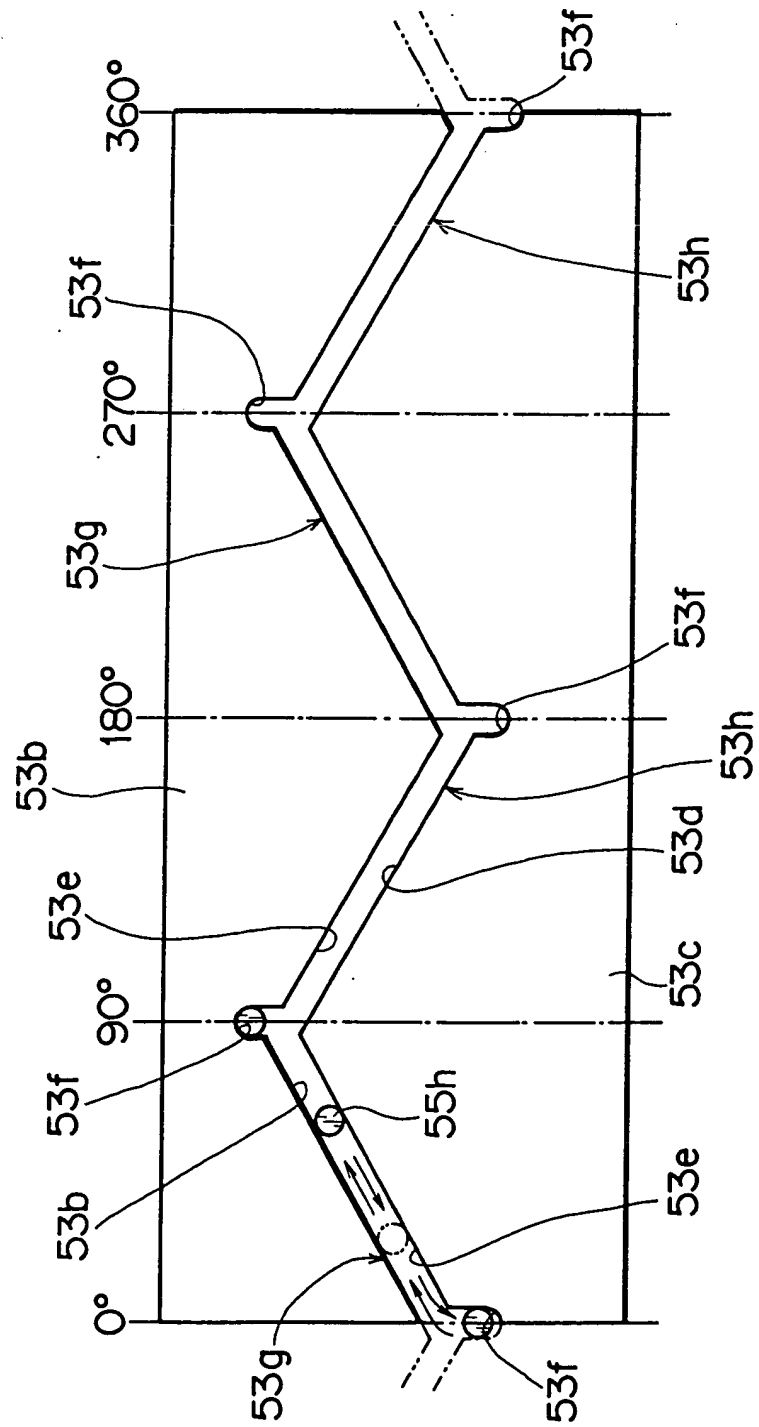


FIG. 49

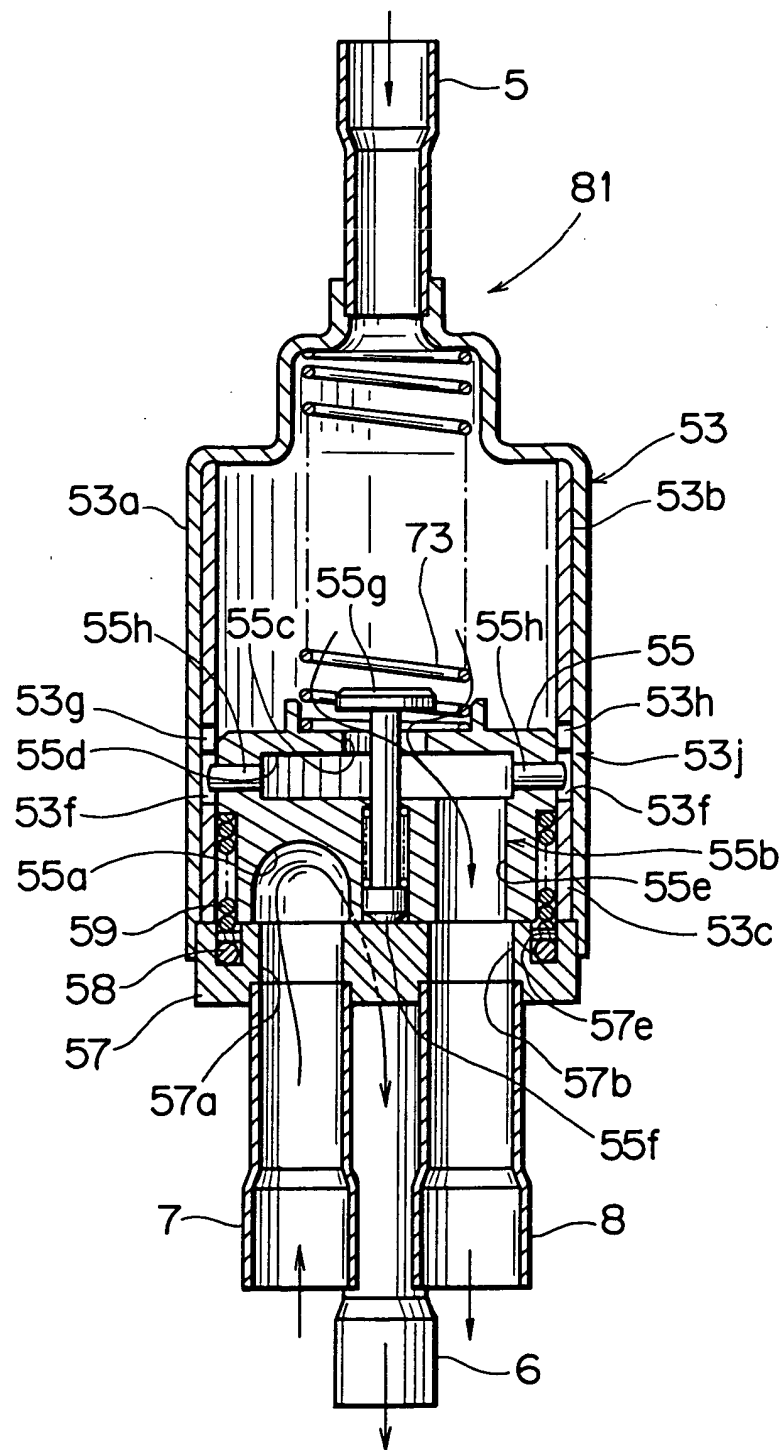


FIG. 50

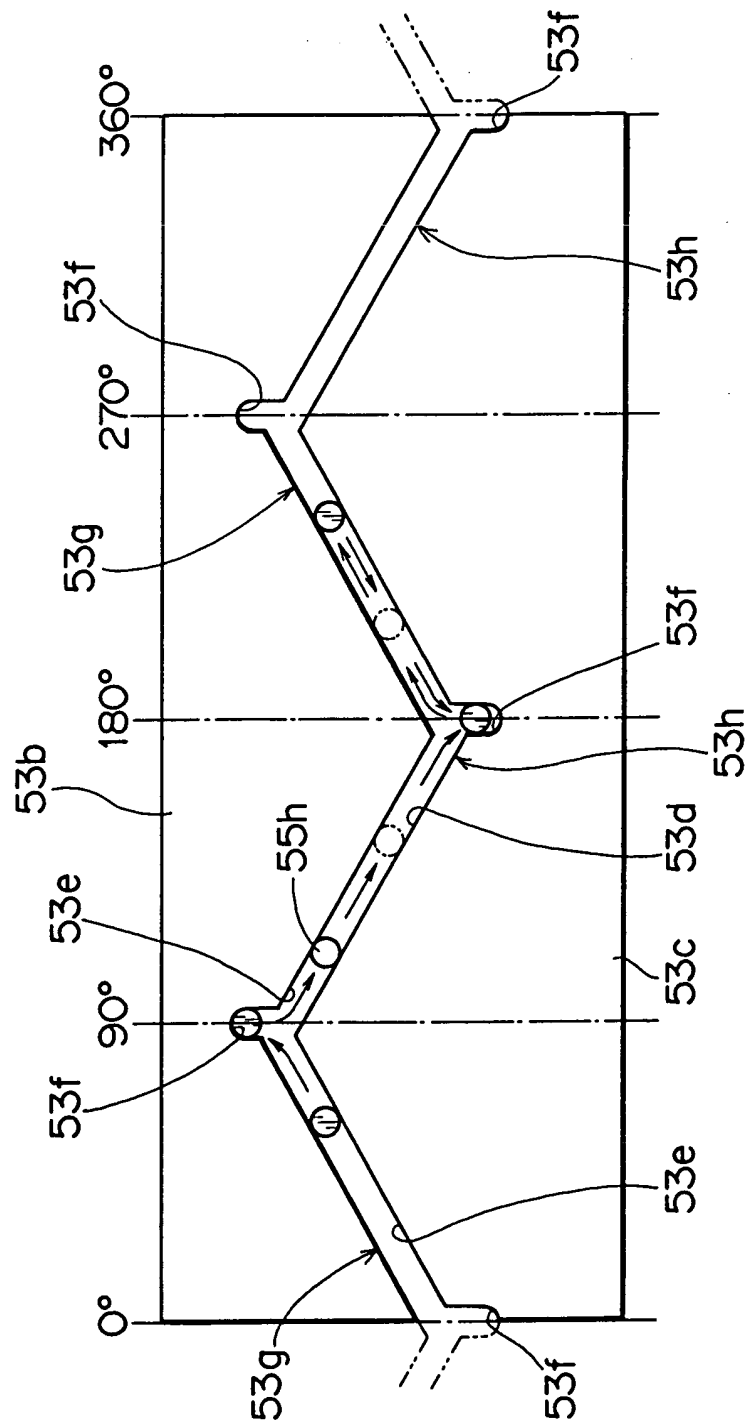


FIG. 51



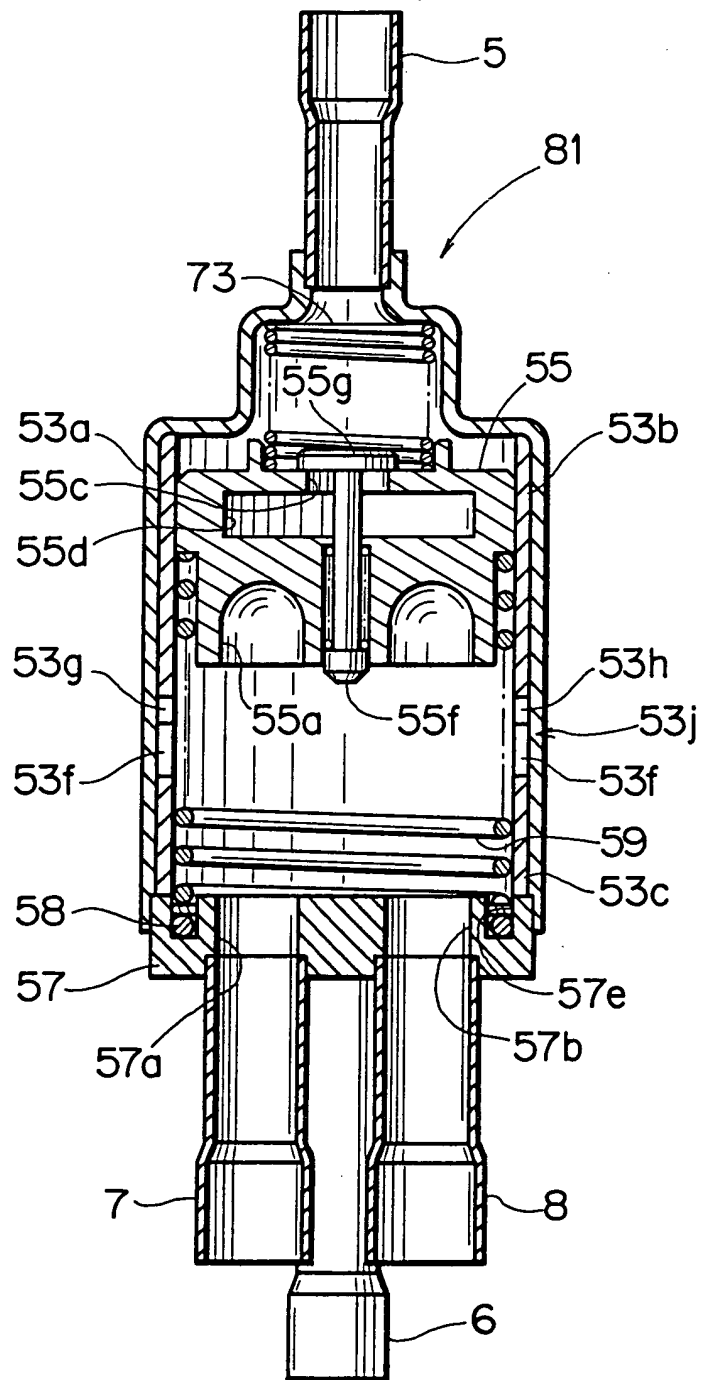


FIG. 52

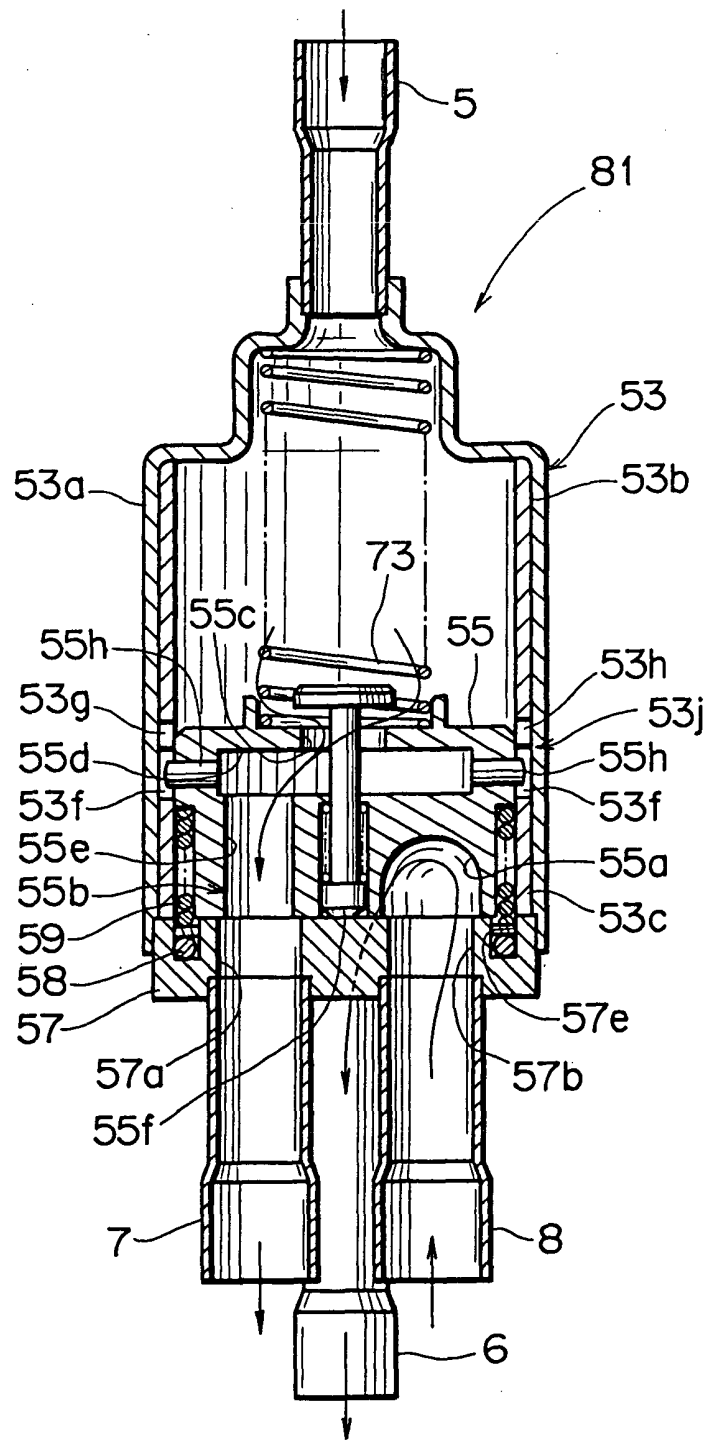


FIG. 53

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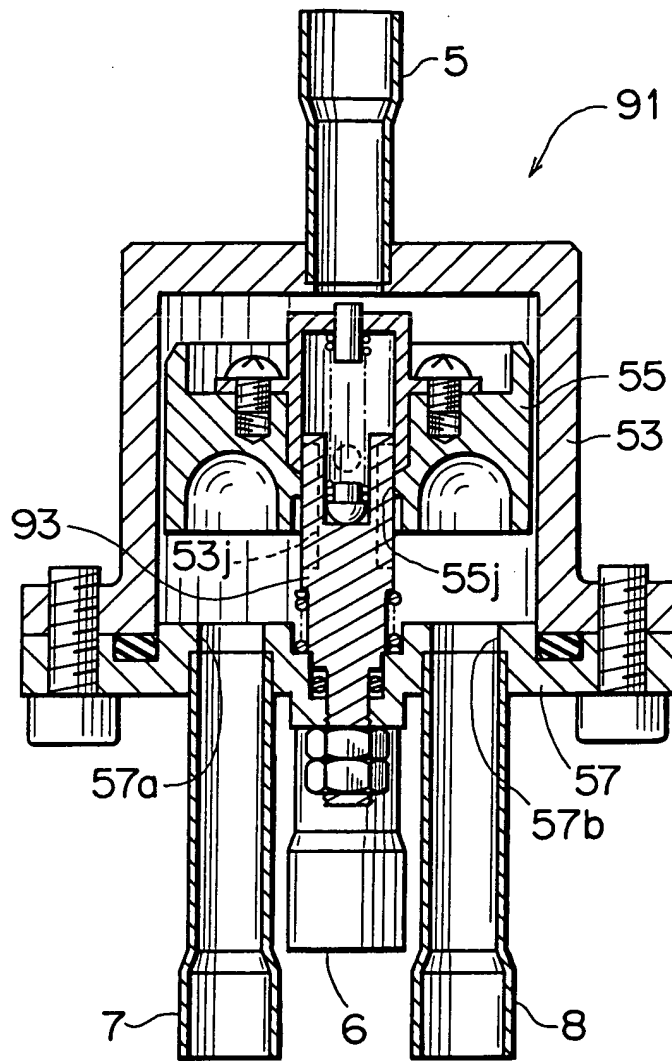


FIG. 54

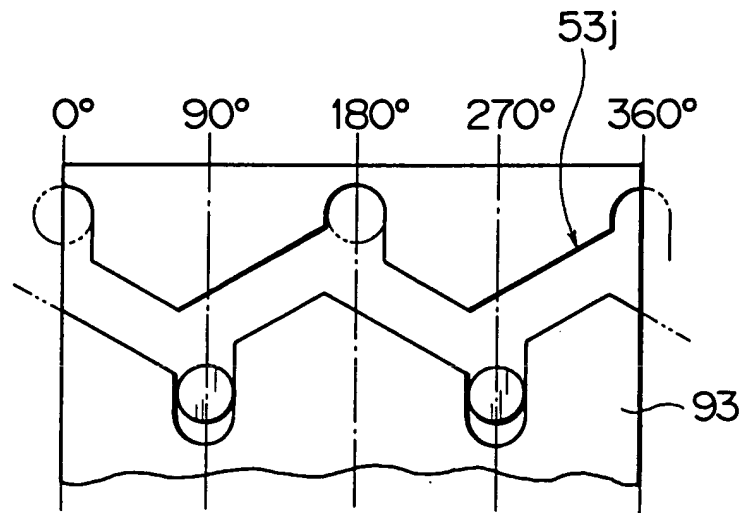


FIG. 56

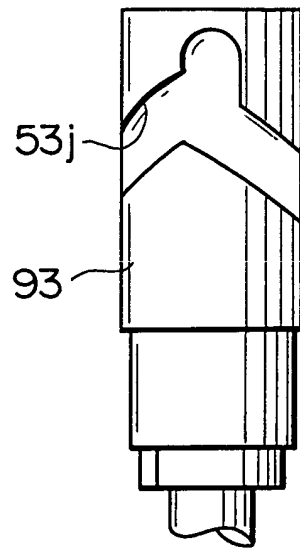


FIG. 55

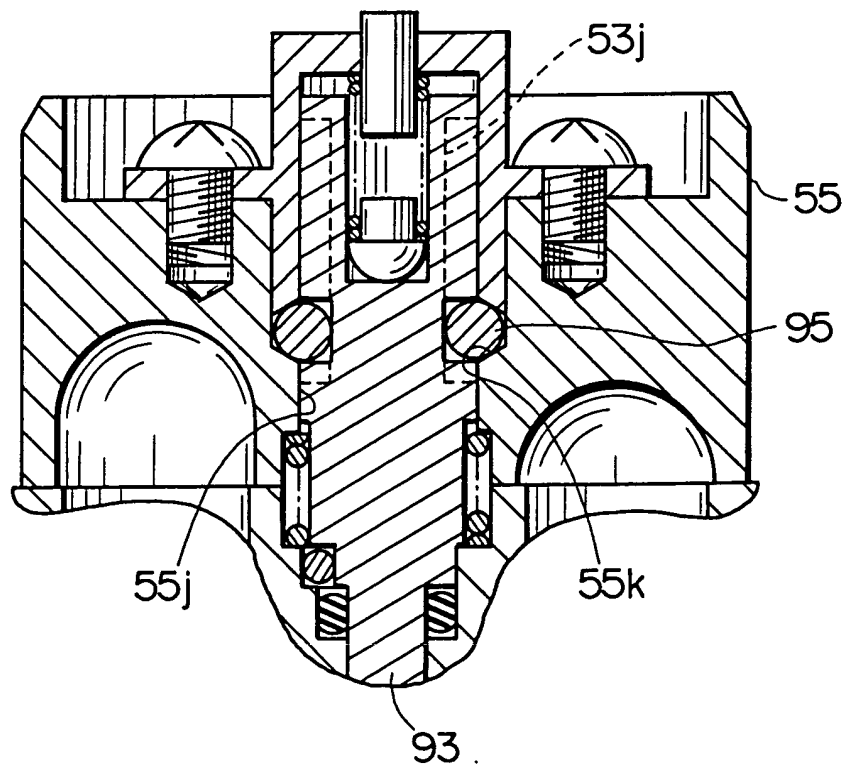


FIG. 57

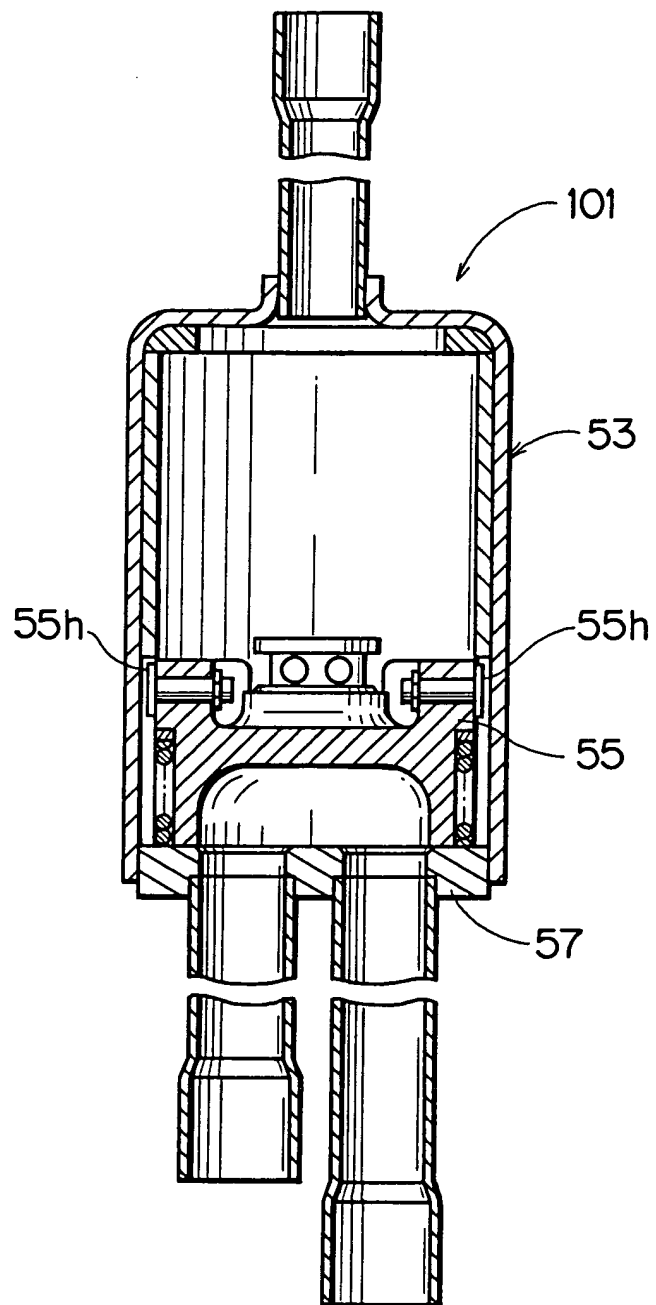


FIG. 58

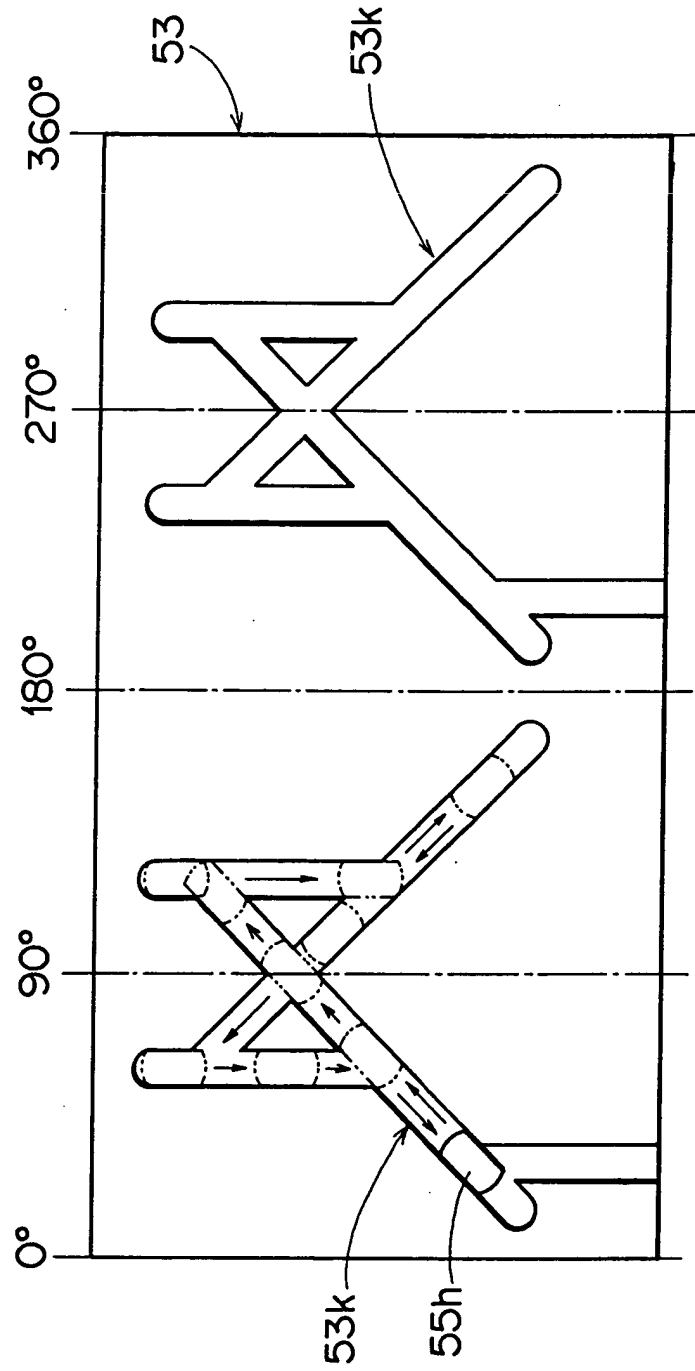


FIG. 59

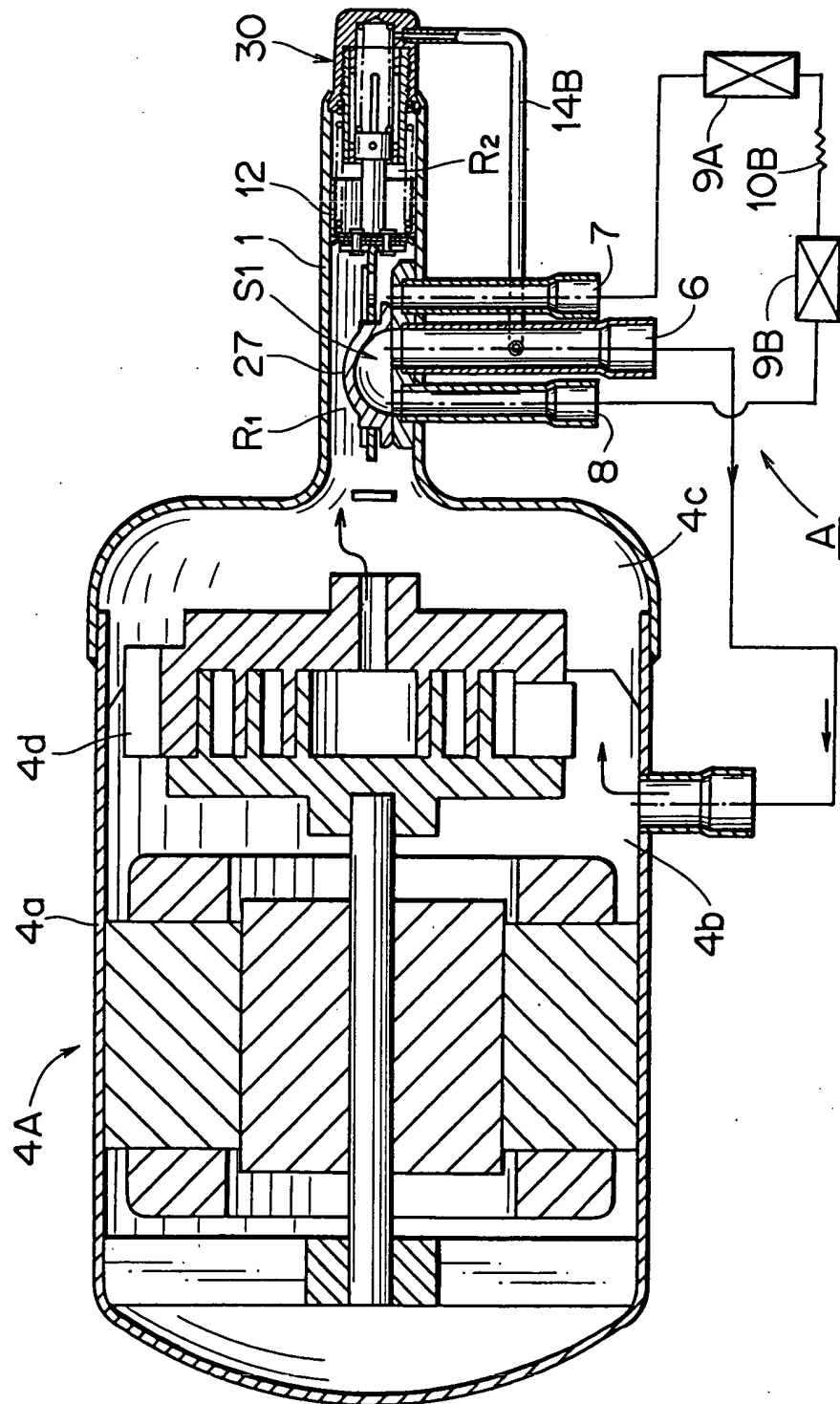


FIG. 60

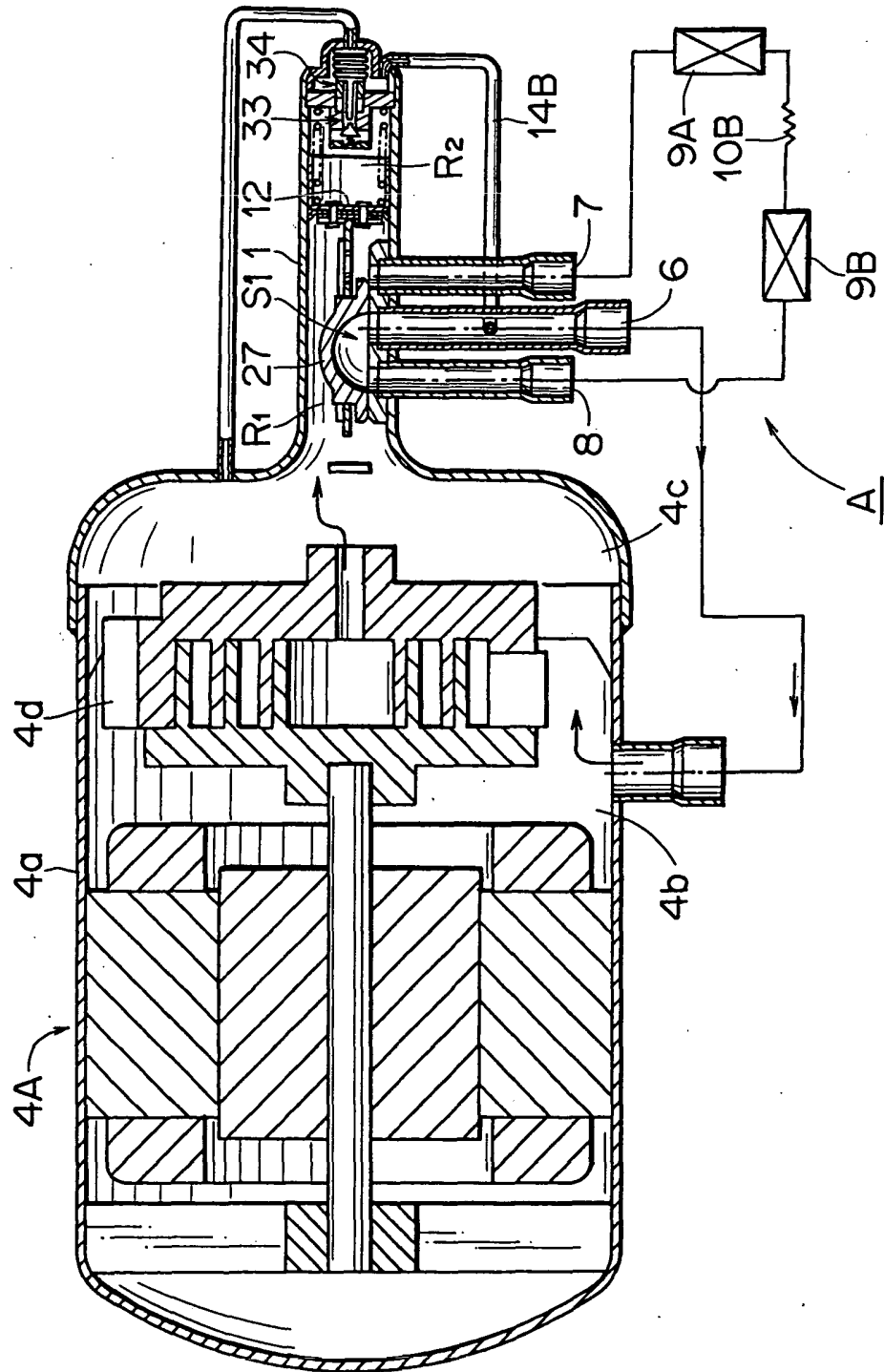


FIG. 61



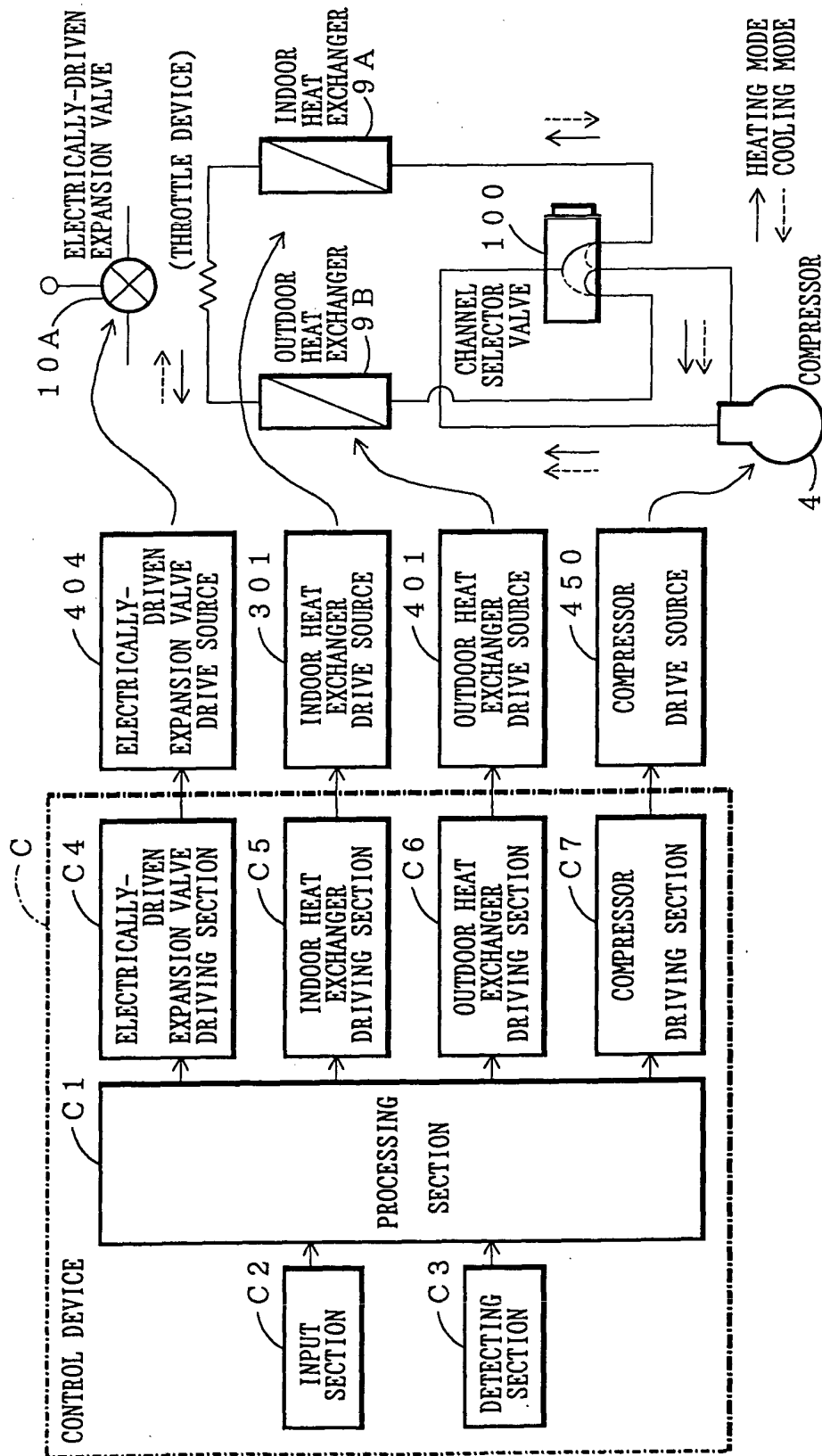


FIG. 62

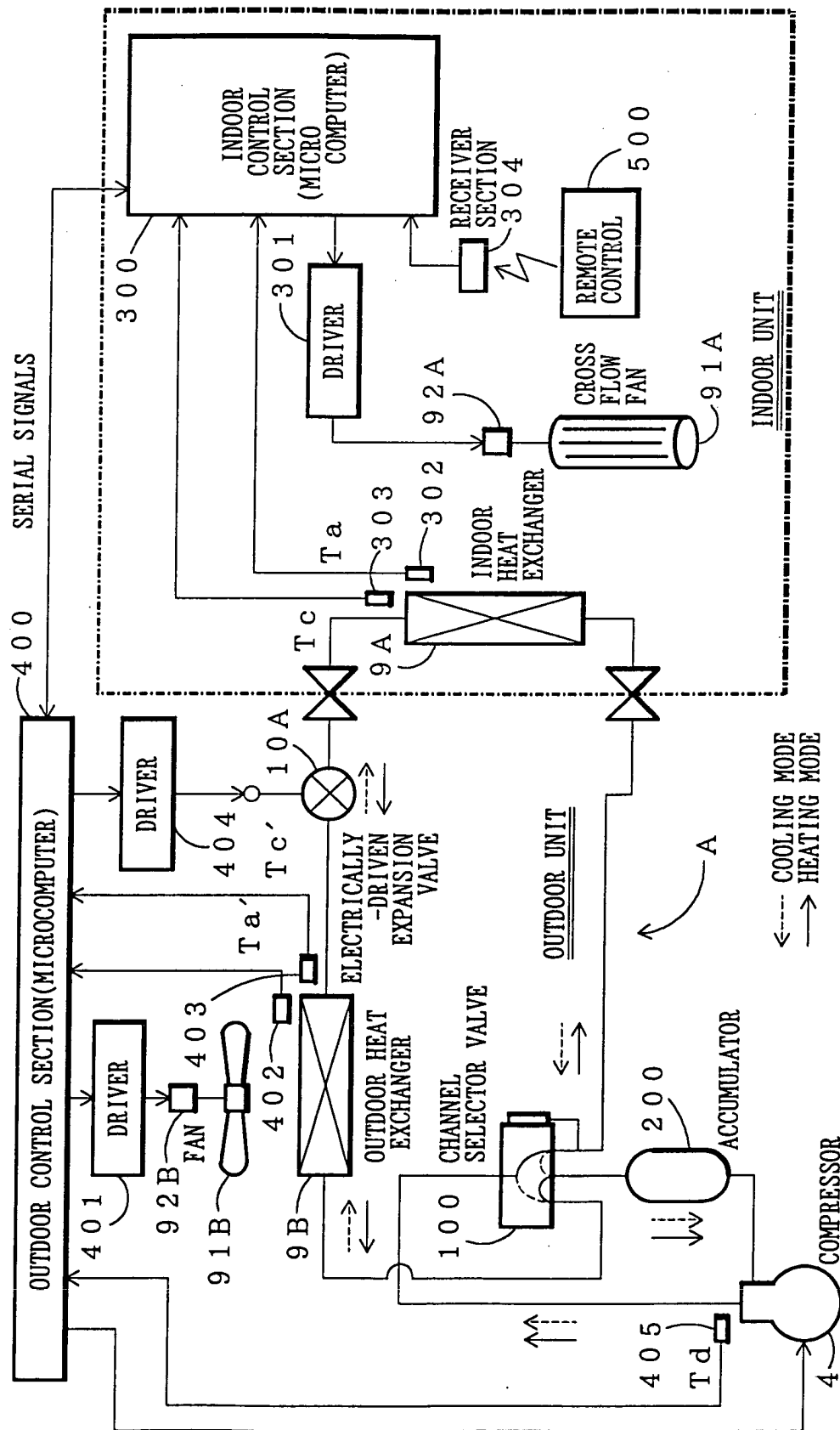


FIG. 63

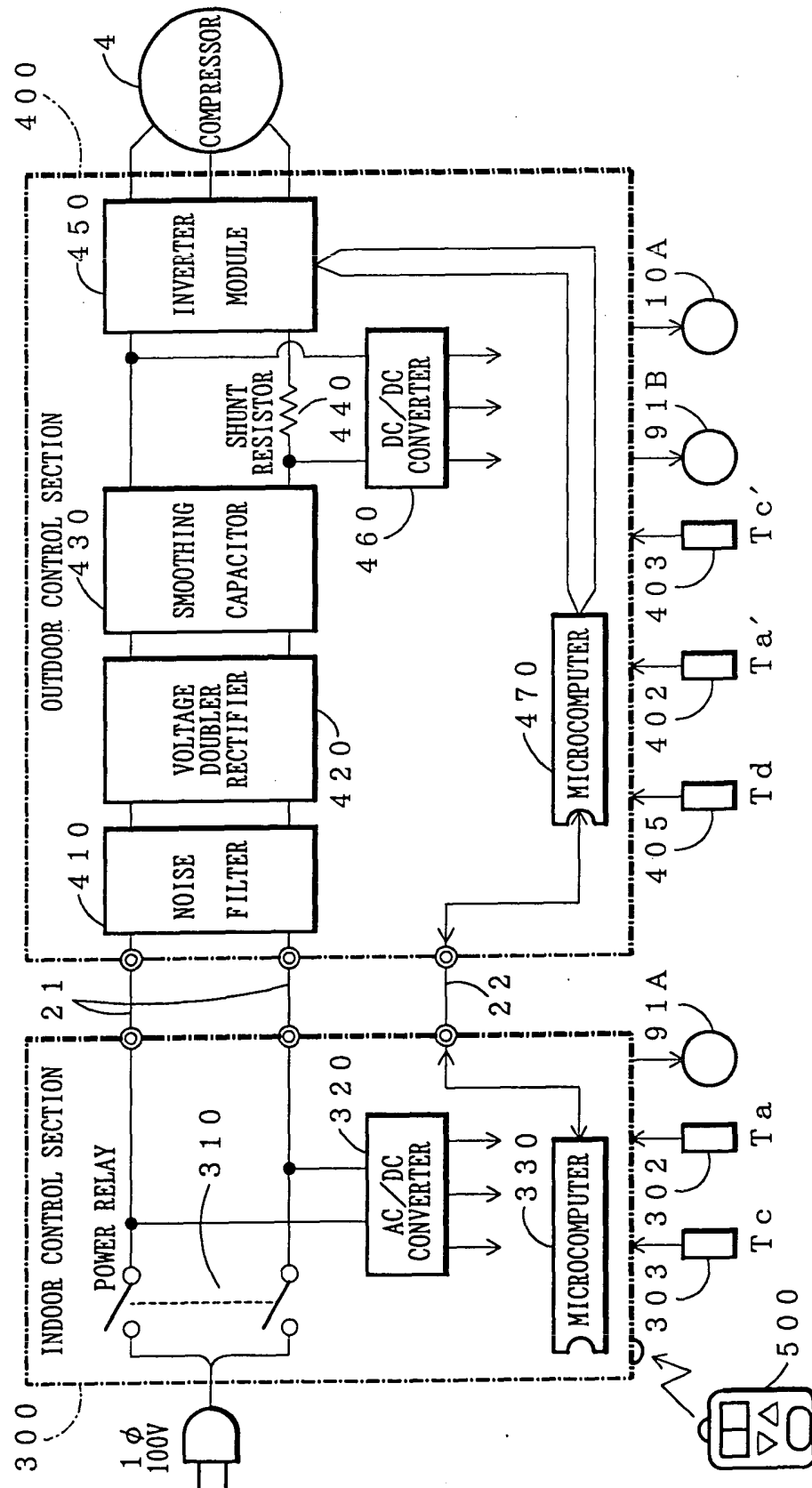


FIG. 64

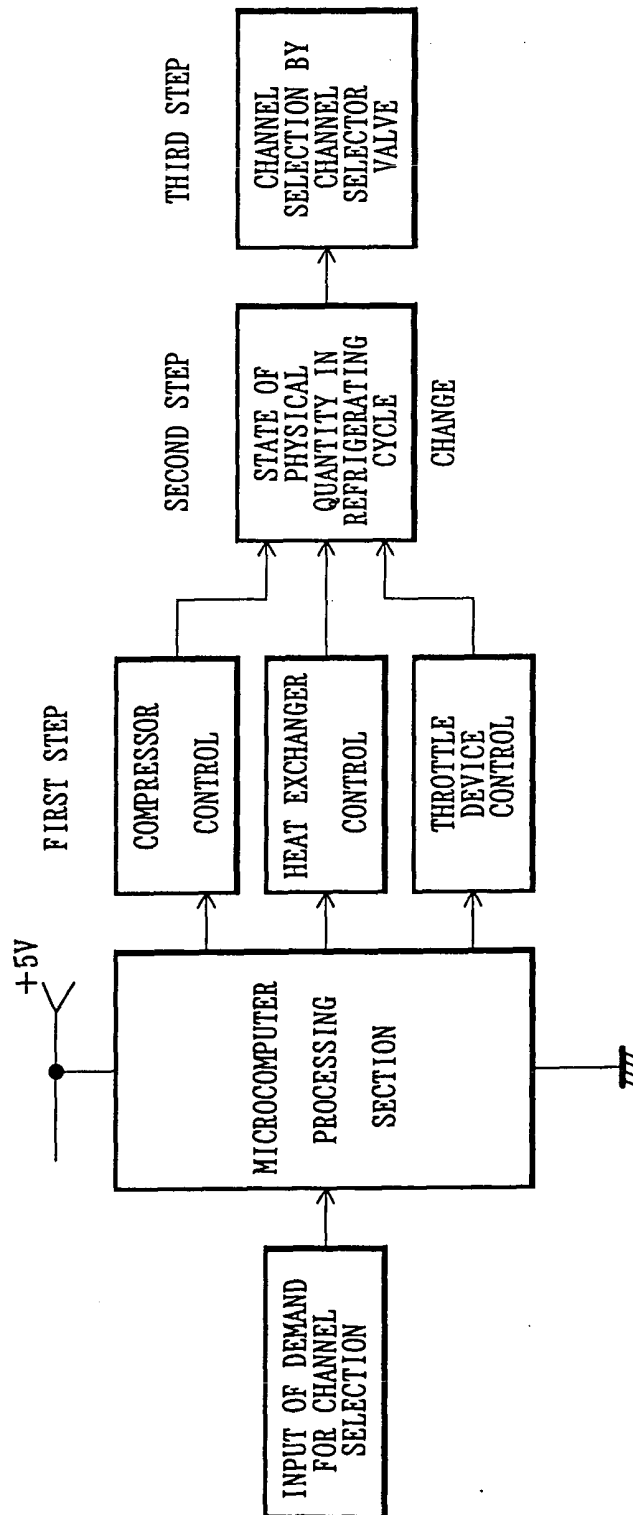


FIG. 65

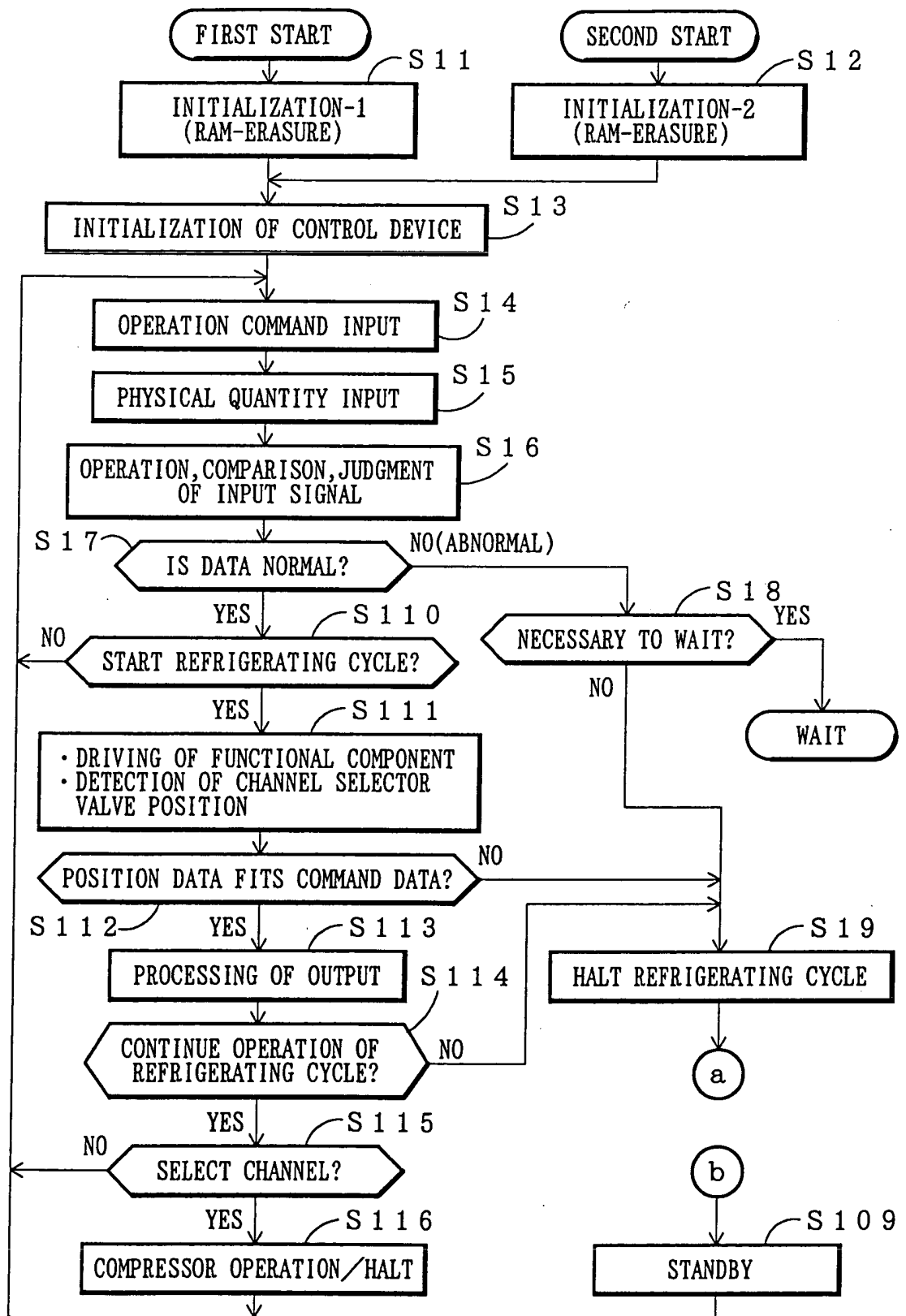


FIG. 66

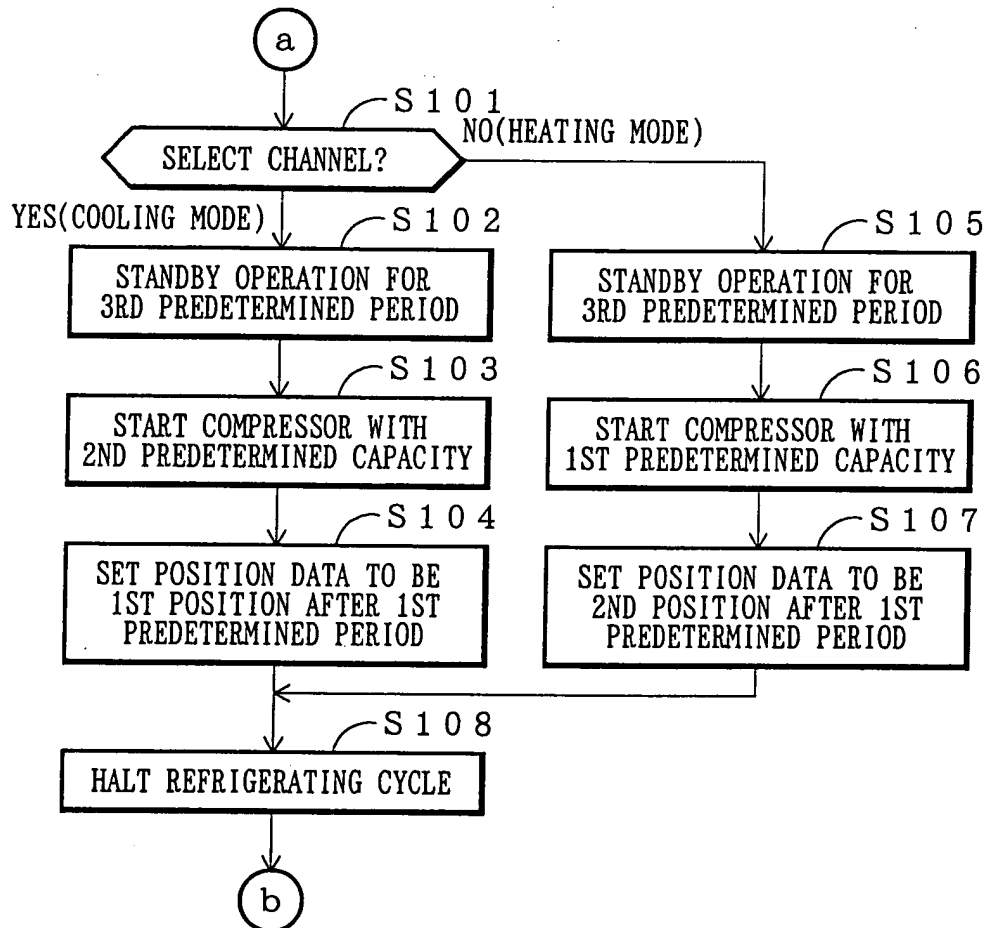


FIG. 67

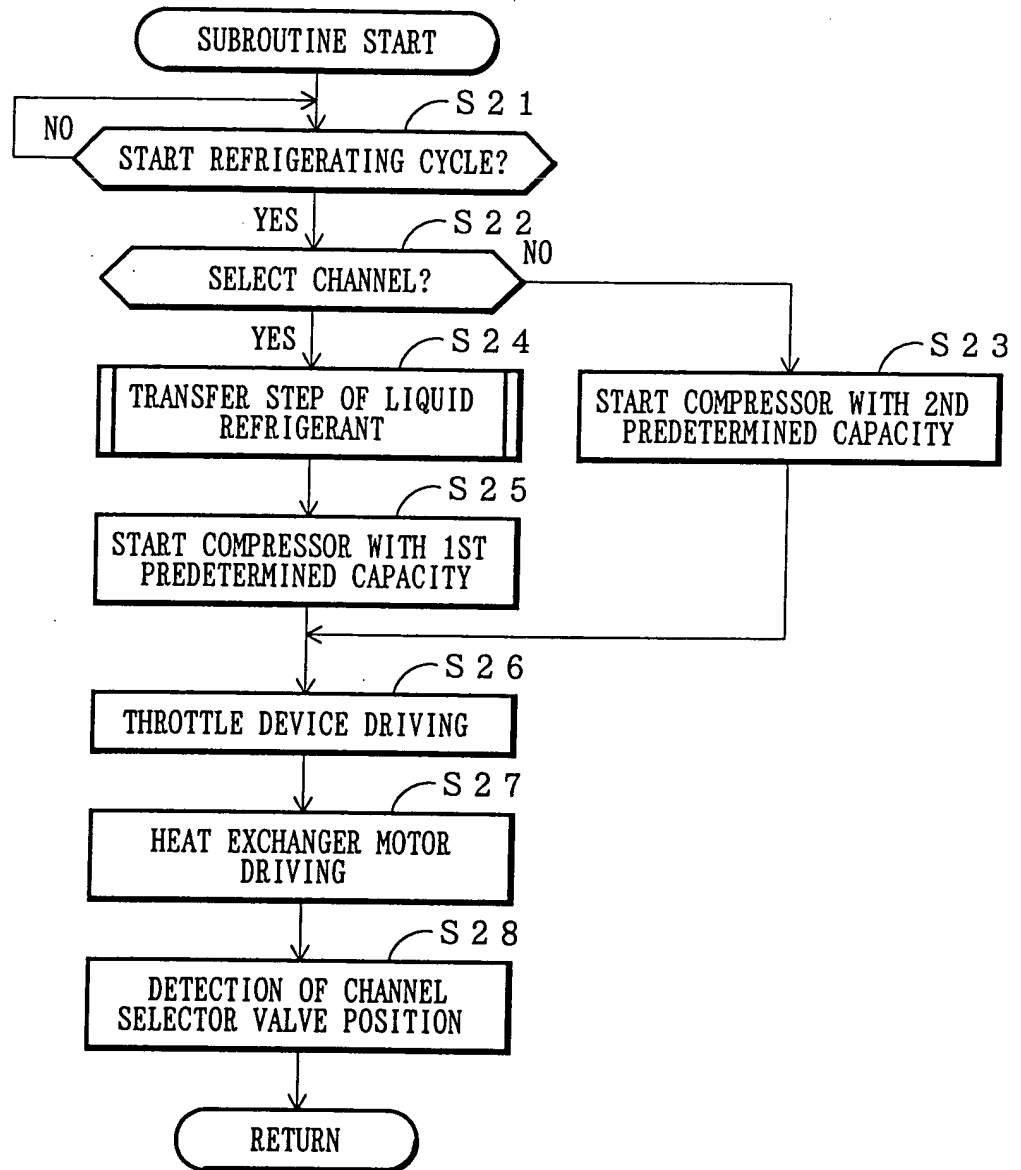


FIG. 68

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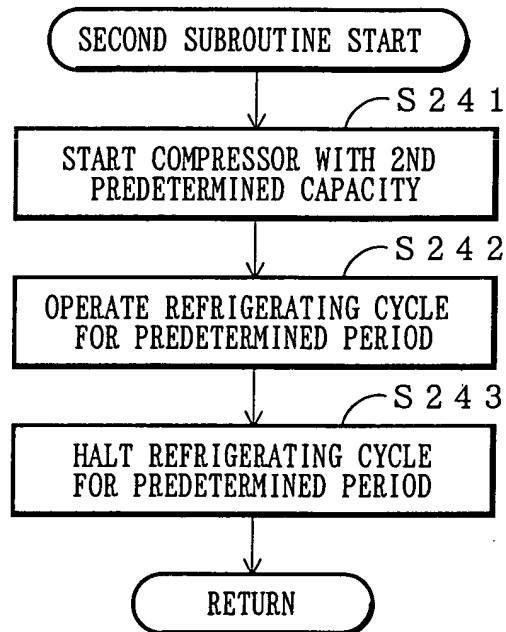


FIG. 69



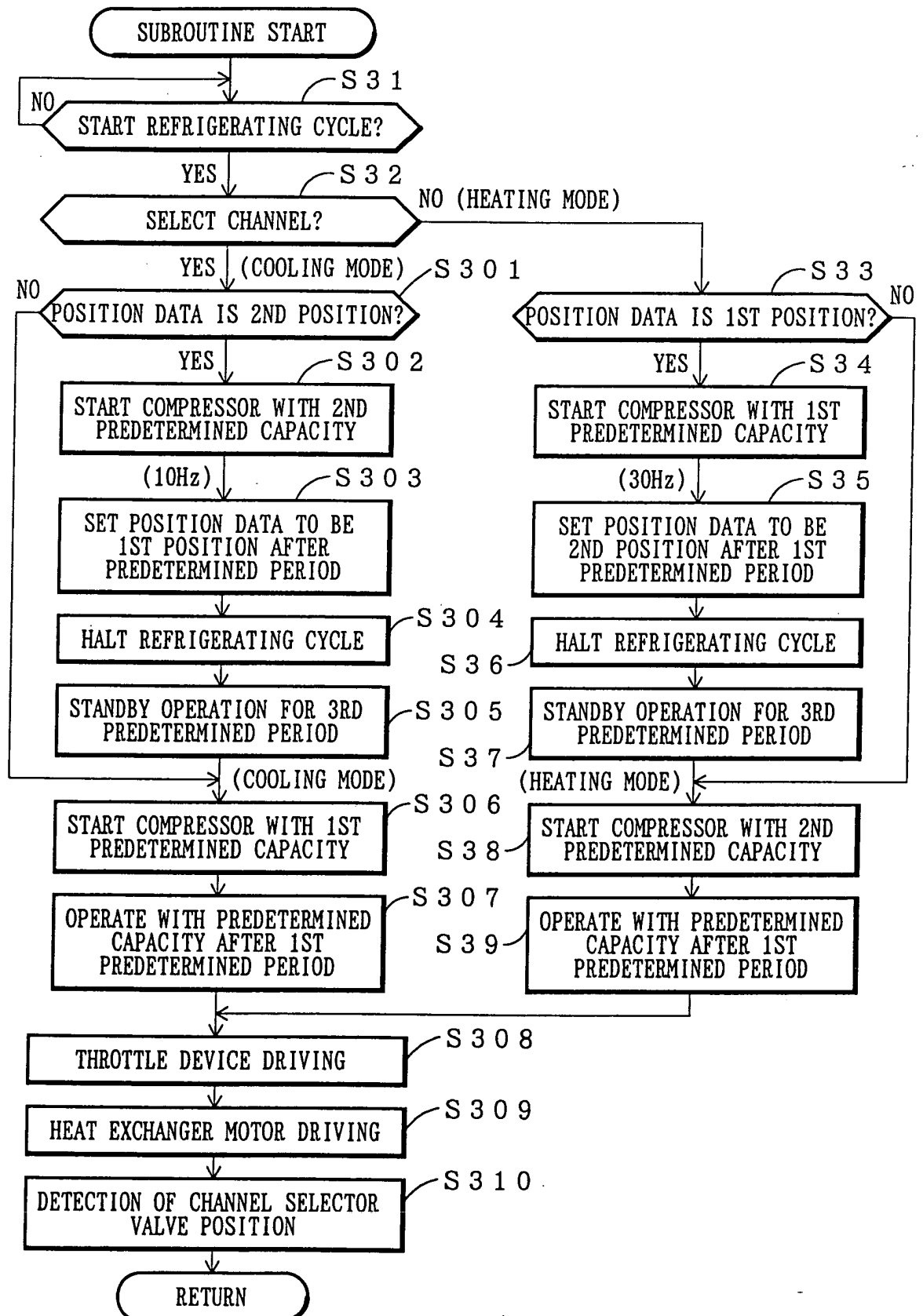


FIG. 70

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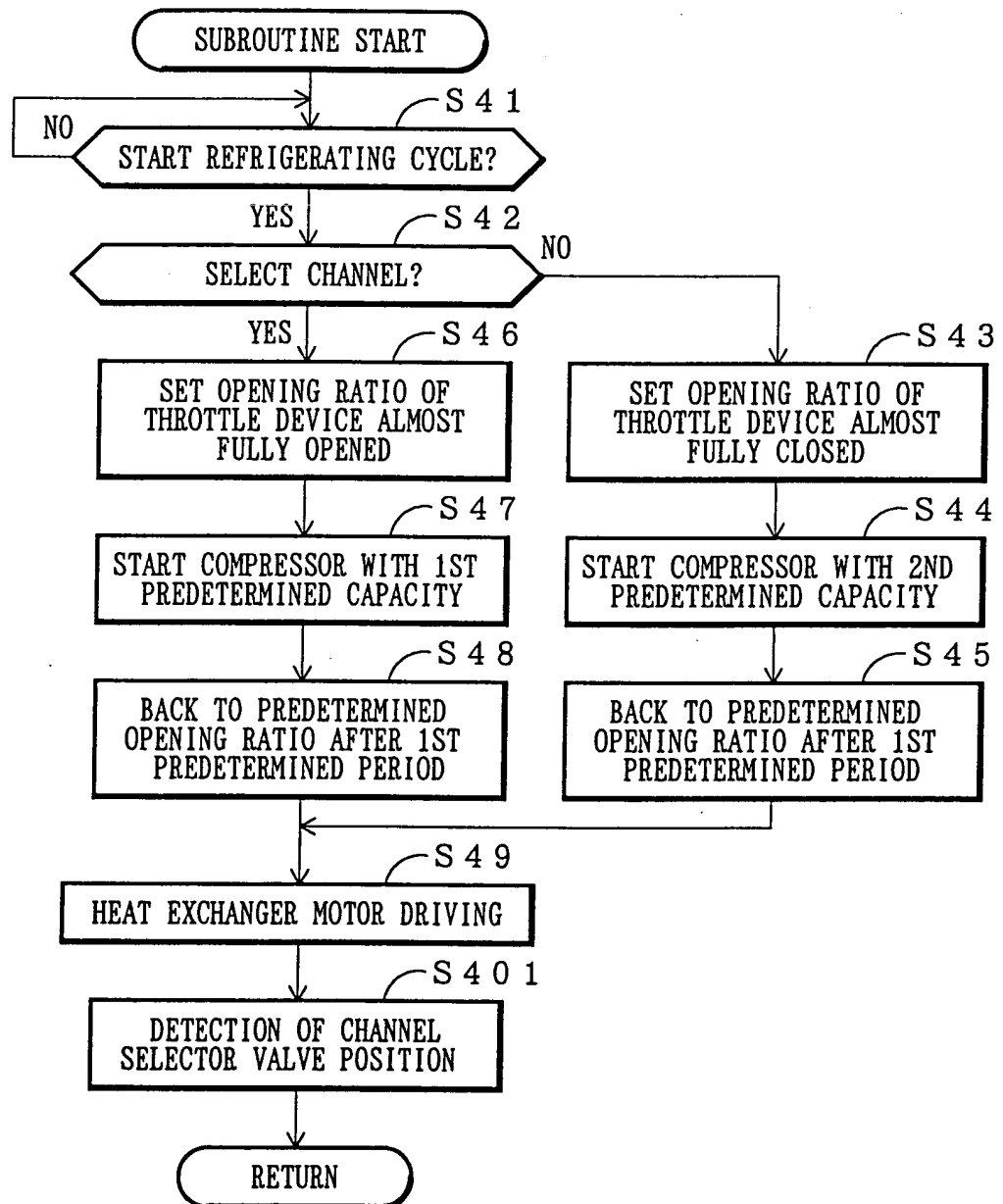


FIG. 71

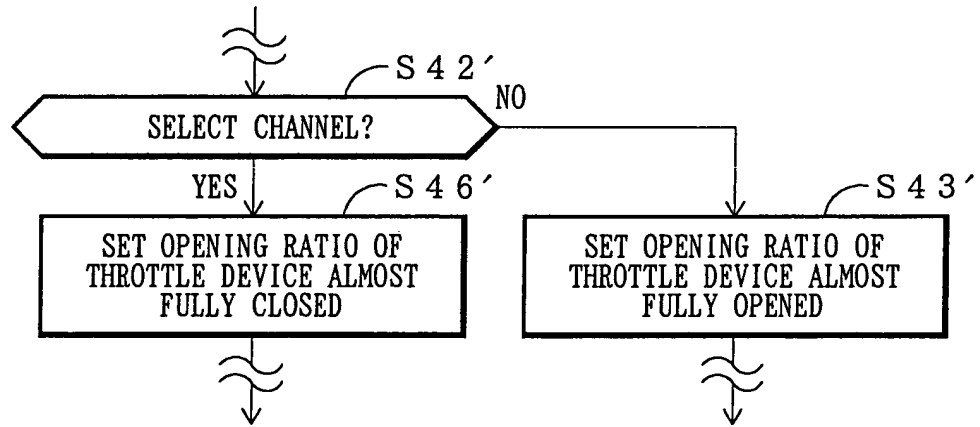


FIG. 72

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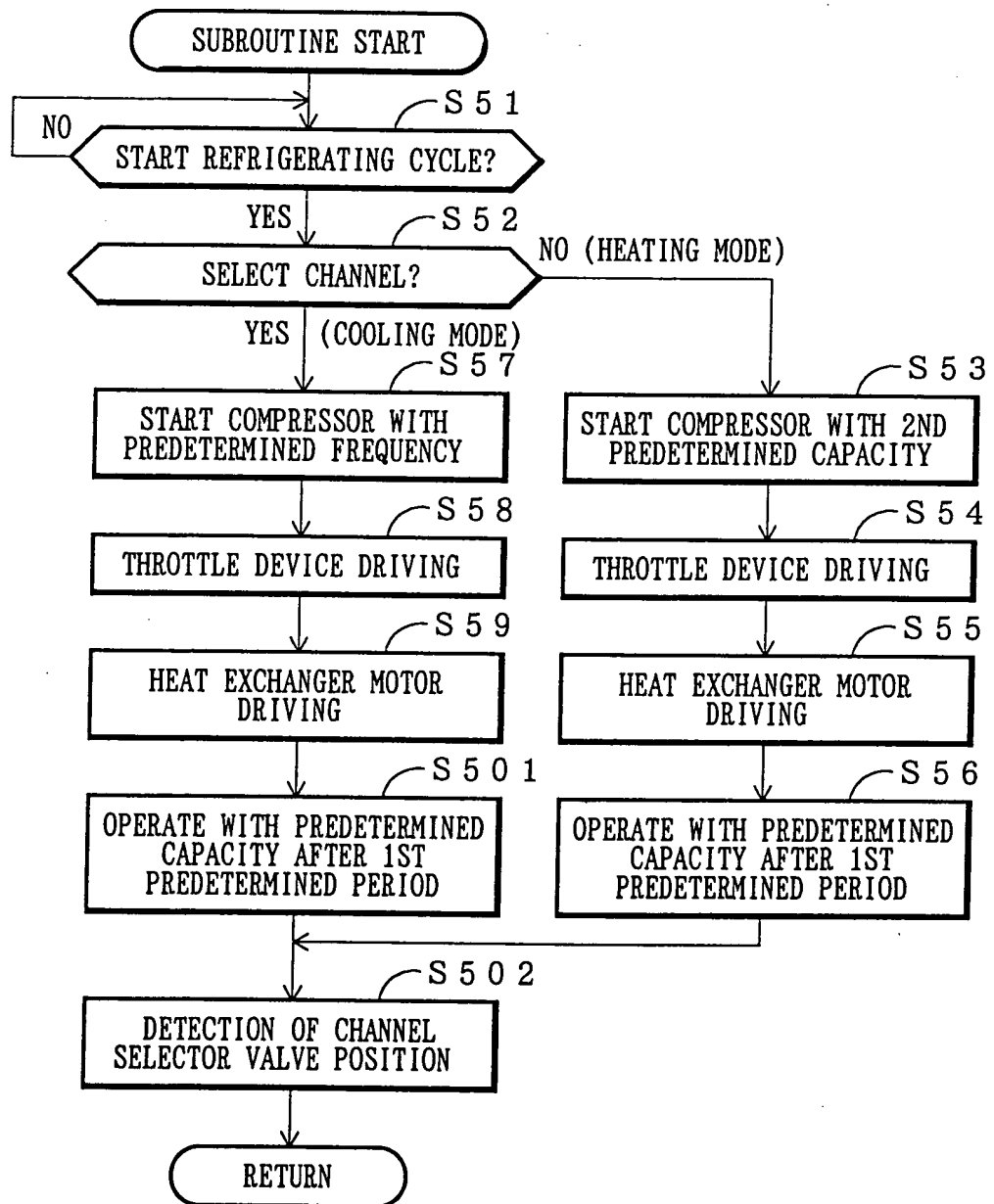


FIG. 73

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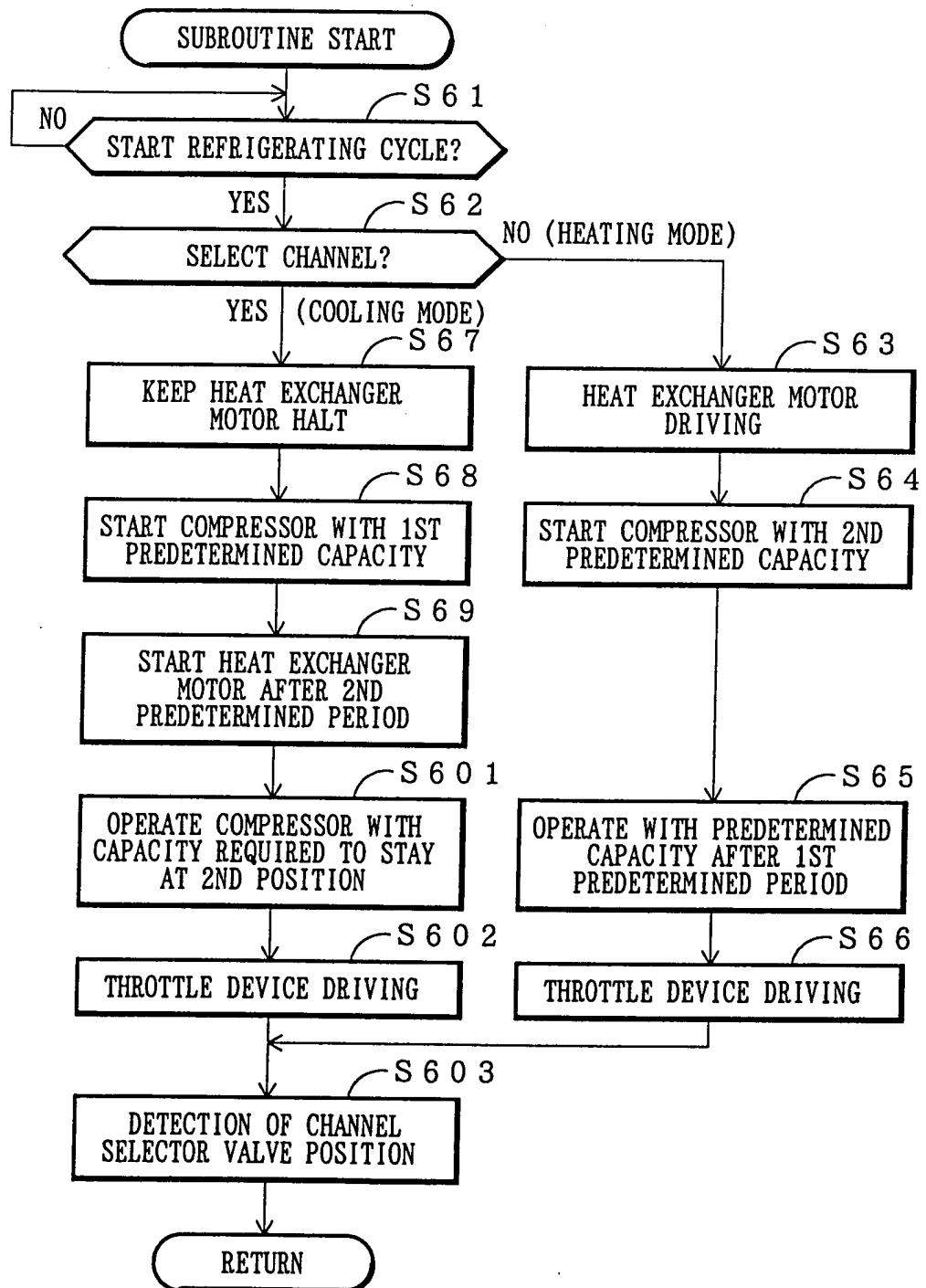


FIG. 74

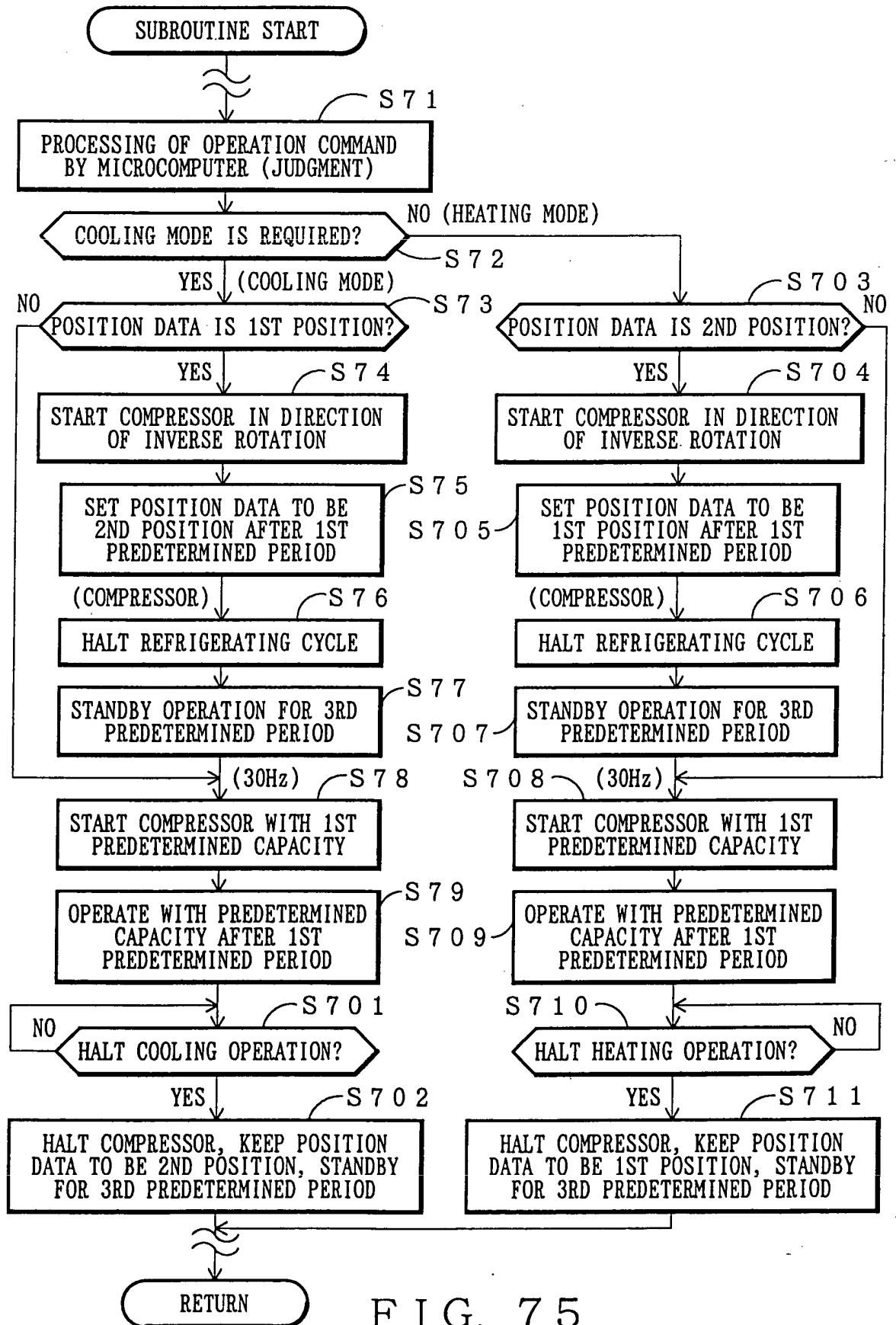


FIG. 75